

High-Performance 6-Axis MEMS MotionTracking™ Device

**GENERAL DESCRIPTION**

The MPU-6886 is a 6-axis MotionTracking device that combines a 3-axis gyroscope and a 3-axis accelerometer in a small 3 mm x 3 mm x 0.75 mm 24-pin LGA package.

- High performance specs:
  - Gyroscope sensitivity error:  $\pm 1\%$
  - Gyroscope noise:  $\pm 4$  mdps/vHz
  - Accelerometer noise:  $100 \mu\text{g}/\text{vHz}$
- Includes 1 kB FIFO to reduce traffic on the serial bus interface, and reduce power consumption by allowing the system processor to burst read sensor data and then go into low-power mode
- EIS FSYNC support

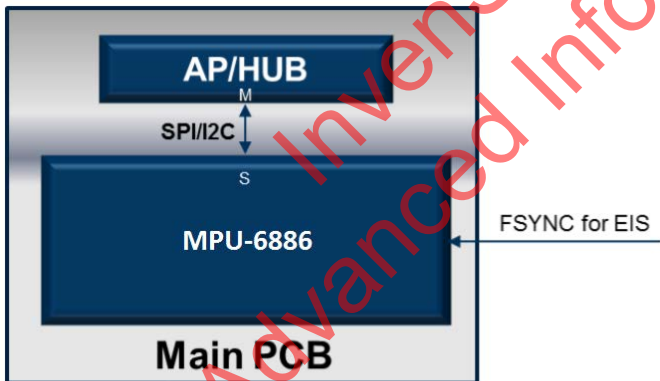
MPU-6886 includes on-chip 16-bit ADC's, programmable digital filters, an embedded temperature sensor, and programmable interrupts. The device features an operating voltage range down to 1.71V. Communication ports include I<sup>2</sup>C and high speed SPI at 10 MHz.

**ORDERING INFORMATION**

PART	TEMP RANGE	PACKAGE
MPU-6886†	-40°C to +85°C	24-Pin LGA

†Denotes RoHS and Green-Compliant Package

**BLOCK DIAGRAM**



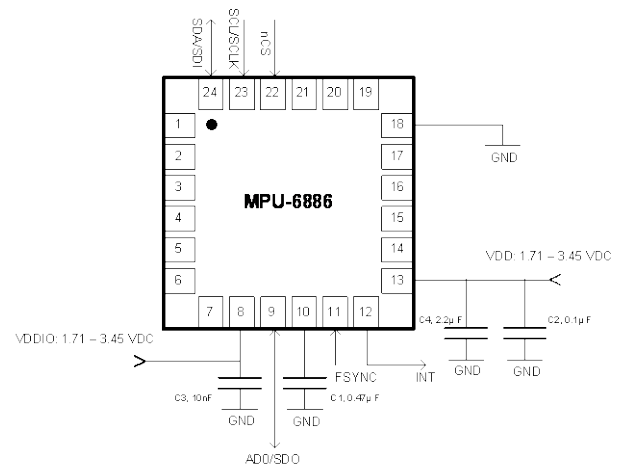
**APPLICATIONS**

- Smartphones and Tablets
- Wearable sensors
- IoT Applications
- Motion-based game controllers
- 3D remote controls for Internet connected DTVs and set top boxes, 3D mice

**FEATURES**

- 3-Axis gyroscope with programmable FSR of  $\pm 250$  dps,  $\pm 500$  dps,  $\pm 1000$  dps, and  $\pm 2000$  dps
- 3-Axis accelerometer with programmable FSR of  $\pm 2g$ ,  $\pm 4g$ ,  $\pm 8g$ , and  $\pm 16g$
- User-programmable interrupts
- Wake-on-motion interrupt for low power operation of applications processor
- 1 kB FIFO buffer enables the applications processor to read the data in bursts
- On-Chip 16-bit ADCs and Programmable Filters
- Host interface: 10 MHz SPI or 400 kHz I<sup>2</sup>C
- Digital-output temperature sensor
- VDD operating range of 1.71V to 3.45V
- MEMS structure hermetically sealed and bonded at wafer level
- RoHS and Green compliant

**TYPICAL OPERATING CIRCUIT**



**TABLE OF CONTENTS**

GENERAL DESCRIPTION ..... 1

ORDERING INFORMATION ..... 1

APPLICATIONS ..... 1

FEATURES ..... 1

TYPICAL OPERATING CIRCUIT ..... 1

**1 INTRODUCTION.....7**

1.1 PURPOSE AND SCOPE ..... 7

1.2 PRODUCT OVERVIEW ..... 7

1.3 APPLICATIONS..... 7

**2 FEATURES ..... 8**

2.1 GYROSCOPE FEATURES ..... 8

2.2 ACCELEROMETER FEATURES..... 8

2.3 ADDITIONAL FEATURES ..... 8

**3 ELECTRICAL CHARACTERISTICS..... 9**

3.1 GYROSCOPE SPECIFICATIONS..... 9

3.2 ACCELEROMETER SPECIFICATIONS..... 10

3.3 ELECTRICAL SPECIFICATIONS..... 11

3.4 I<sup>2</sup>C TIMING CHARACTERIZATION ..... 14

3.5 SPI TIMING CHARACTERIZATION..... 15

3.6 ABSOLUTE MAXIMUM RATINGS ..... 16

**4 APPLICATIONS INFORMATION ..... 17**

4.1 PIN OUT DIAGRAM AND SIGNAL DESCRIPTION ..... 17

4.2 TYPICAL OPERATING CIRCUIT ..... 18

4.3 BILL OF MATERIALS FOR EXTERNAL COMPONENTS ..... 18

4.4 EXPOSED DIE PAD PRECAUTIONS..... 18

4.5 BLOCK DIAGRAM ..... 19

4.6 OVERVIEW ..... 19

4.7 THREE-AXIS MEMS GYROSCOPE WITH 16-BIT ADCS AND SIGNAL CONDITIONING ..... 20

4.8 THREE-AXIS MEMS ACCELEROMETER WITH 16-BIT ADCS AND SIGNAL CONDITIONING..... 20

4.9 I2C AND SPI SERIAL COMMUNICATIONS INTERFACES..... 20

4.10 SELF-TEST ..... 21

4.11 CLOCKING ..... 22

4.12 SENSOR DATA REGISTERS..... 22

4.13 FIFO..... 22

4.14 INTERRUPTS..... 22

4.15 DIGITAL-OUTPUT TEMPERATURE SENSOR..... 22

4.16 BIAS AND LDOs ..... 22

4.17 CHARGE PUMP..... 22

4.18 STANDARD POWER MODES ..... 23

**5 PROGRAMMABLE INTERRUPTS..... 24**

5.1 WAKE-ON-MOTION INTERRUPT ..... 24

**6 DIGITAL INTERFACE..... 25**

6.1 I<sup>2</sup>C AND SPI SERIAL INTERFACES ..... 25

6.2	I <sup>2</sup> C INTERFACE .....	25
6.3	I <sup>2</sup> C COMMUNICATIONS PROTOCOL .....	25
6.4	I <sup>2</sup> C TERMS .....	27
6.5	SPI INTERFACE.....	28
<b>7</b>	<b>REGISTER MAP.....</b>	<b>29</b>
<b>8</b>	<b>REGISTER DESCRIPTIONS.....</b>	<b>32</b>
8.1	REGISTER 04 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	32
8.2	REGISTER 05 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	32
8.3	REGISTER 07 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	33
8.4	REGISTER 08 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	33
8.5	REGISTER 10 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	33
8.6	REGISTER 11 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER.....	33
8.7	REGISTERS 13 TO 15 – ACCELEROMETER SELF-TEST REGISTERS.....	34
8.8	REGISTER 19 – X-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE.....	34
8.9	REGISTER 20 – X-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE.....	34
8.10	REGISTER 21 – Y-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE.....	35
8.11	REGISTER 22 – Y-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE.....	35
8.12	REGISTER 23 – Z-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE.....	35
8.13	REGISTER 24 – Z-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE.....	35
8.14	REGISTER 25 – SAMPLE RATE DIVIDER.....	35
8.15	REGISTER 26 – CONFIGURATION .....	36
8.16	REGISTER 27 – GYROSCOPE CONFIGURATION .....	37
8.17	REGISTER 28 – ACCELEROMETER CONFIGURATION.....	37
8.18	REGISTER 29 – ACCELEROMETER CONFIGURATION 2.....	37
8.19	REGISTER 30 – GYROSCOPE LOW POWER MODE CONFIGURATION .....	39
8.20	REGISTER 32 – WAKE-ON MOTION THRESHOLD (X-AXIS ACCELEROMETER).....	39
8.21	REGISTER 33 – WAKE-ON MOTION THRESHOLD (Y-AXIS ACCELEROMETER).....	40
8.22	REGISTER 34 – WAKE-ON MOTION THRESHOLD (Z-AXIS ACCELEROMETER).....	40
8.23	REGISTER 35 – FIFO ENABLE.....	40
8.24	REGISTER 54 – FSYNC INTERRUPT STATUS .....	40
8.25	REGISTER 55 – INT/DRDY PIN / BYPASS ENABLE CONFIGURATION .....	41
8.26	REGISTER 56 – INTERRUPT ENABLE .....	41
8.27	REGISTER 57 – FIFO WATERMARK INTERRUPT STATUS .....	41
8.28	REGISTER 58 – INTERRUPT STATUS .....	42
8.29	REGISTERS 59 TO 64 – ACCELEROMETER MEASUREMENTS.....	42
8.30	REGISTERS 65 AND 66 – TEMPERATURE MEASUREMENT .....	43
8.31	REGISTERS 67 TO 72 – GYROSCOPE MEASUREMENTS.....	43
8.32	REGISTERS 80 TO 82 – GYROSCOPE SELF-TEST REGISTERS.....	44
8.33	REGISTERS 83 TO 90 – ENGINEERING ID REGISTERS .....	44
8.34	REGISTER 96-97 – FIFO WATERMARK THRESHOLD IN NUMBER OF BYTES .....	45
8.35	REGISTER 104 – SIGNAL PATH RESET .....	46
8.36	REGISTER 105 – ACCELEROMETER INTELLIGENCE CONTROL .....	46
8.37	REGISTER 106 – USER CONTROL .....	46

8.38	REGISTER 107 – POWER MANAGEMENT 1 .....	47
8.39	REGISTER 108 – POWER MANAGEMENT 2 .....	47
8.40	REGISTER 112 – I <sup>2</sup> C INTERFACE .....	48
8.41	REGISTER 114 AND 115 – FIFO COUNT REGISTERS .....	48
8.42	REGISTER 116 – FIFO READ WRITE .....	48
8.43	REGISTER 117 – WHO AM I .....	49
8.44	REGISTERS 119, 120, 122, 123, 125, 126 ACCELEROMETER OFFSET REGISTERS .....	49
<b>9</b>	<b>USE NOTES .....</b>	<b>51</b>
9.1	ACCELEROMETER-ONLY LOW-NOISE MODE .....	51
9.2	ACCELEROMETER LOW-POWER MODE .....	51
9.3	SENSOR MODE CHANGE .....	51
9.4	TEMP SENSOR DURING GYROSCOPE STANDBY MODE .....	51
9.5	GYROSCOPE MODE CHANGE .....	51
9.6	POWER MANAGEMENT 1 REGISTER SETTING .....	51
9.7	UNLISTED REGISTER LOCATIONS .....	51
9.8	CLOCK TRANSITION WHEN GYROSCOPE IS TURNED OFF .....	51
9.9	SLEEP MODE .....	52
9.10	NO SPECIAL OPERATION NEEDED FOR FIFO READ IN LOW POWER MODE .....	52
9.11	GYROSCOPE STANDBY PROCEDURE .....	52
<b>10</b>	<b>ASSEMBLY .....</b>	<b>53</b>
10.1	ORIENTATION OF AXES .....	53
10.2	PACKAGE DIMENSIONS .....	54
<b>11</b>	<b>PART NUMBER PACKAGE MARKING .....</b>	<b>55</b>
<b>12</b>	<b>REFERENCE .....</b>	<b>56</b>
<b>13</b>	<b>DOCUMENT INFORMATION .....</b>	<b>57</b>
13.1	REVISION HISTORY .....	57

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**Table of Figures**

Figure 1. I<sup>2</sup>C Bus Timing Diagram .....14  
 Figure 2. SPI Bus Timing Diagram .....15  
 Figure 3. Pin out Diagram for MPU-6886 3.0 mm x 3.0 mm x 0.75 mm LGA .....17  
 Figure 4. MPU-6886 LGA Example Application Schematic .....18  
 Figure 5. MPU-6886 Block Diagram .....19  
 Figure 6. MPU-6886 Solution Using I<sup>2</sup>C Interface .....20  
 Figure 7. MPU-6886 Solution Using SPI Interface .....21  
 Figure 8. START and STOP Conditions .....25  
 Figure 9. Acknowledge on the I<sup>2</sup>C Bus .....26  
 Figure 10. Complete I<sup>2</sup>C Data Transfer .....26  
 Figure 11. Typical SPI Master/Slave Configuration .....28  
 Figure 12. Orientation of Axes of Sensitivity and Polarity of Rotation .....53  
 Figure 13. Package Diagram .....54  
 Figure 14. Part Number Package Marking .....55

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**Table of Tables**

Table 1. Gyroscope Specifications .....9

Table 2. Accelerometer Specifications .....10

Table 3. D.C. Electrical Characteristics .....11

Table 4. A.C. Electrical Characteristics .....13

Table 5. Other Electrical Specifications .....13

Table 6. I<sup>2</sup>C Timing Characteristics .....14

Table 7. SPI Timing Characteristics (10 MHz Operation) .....15

Table 8. Absolute Maximum Ratings .....16

Table 9. Signal Descriptions .....17

Table 10. Bill of Materials .....18

Table 11. Standard Power Modes for MPU-6886 .....23

Table 12. Table of Interrupt Sources .....24

Table 13. Serial Interface .....25

Table 14. I<sup>2</sup>C Terms .....27

Table 15. MPU-6886 Register Map .....31

Table 16. Configuration .....36

Table 17. Accelerometer Data Rates and Bandwidths (Low-Noise Mode) .....38

Table 18. Approximate Accelerometer Filter Bandwidths (Low-Power Mode) .....38

Table 19. Example Gyroscope Configurations (Low-Power Mode) .....39

Table 20. Package Dimensions .....54

Table 21. Part Number Package Marking .....55

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## 1 INTRODUCTION

### 1.1 PURPOSE AND SCOPE

This document is a product specification, providing a description, specifications, and design related information on the MPU-6886™ MotionTracking device. The device is housed in a small 3x3x0.75mm 24-pin LGA package.

### 1.2 PRODUCT OVERVIEW

The MPU-6886 is a 6-axis MotionTracking device that combines a 3-axis gyroscope, 3-axis accelerometer, in a small 3 mm x 3 mm x 0.75 mm (24-pin LGA) package. It also features a 1 kB FIFO that can lower the traffic on the serial bus interface, and reduce power consumption by allowing the system processor to burst read sensor data and then go into a low-power mode. MPU-6886, with its 6-axis integration, enables manufacturers to eliminate the costly and complex selection, qualification, and system level integration of discrete devices, guaranteeing optimal motion performance for consumers.

The gyroscope has a programmable full-scale range of  $\pm 250$  dps,  $\pm 500$  dps,  $\pm 1000$  dps, and  $\pm 2000$  dps. The accelerometer has a user-programmable accelerometer full-scale range of  $\pm 2g$ ,  $\pm 4g$ ,  $\pm 8g$ , and  $\pm 16g$ . Factory-calibrated initial sensitivity of both sensors reduces production-line calibration requirements.

Other industry-leading features include on-chip 16-bit ADCs, programmable digital filters, an embedded temperature sensor, and programmable interrupts. The device features I<sup>2</sup>C and SPI serial interfaces, a VDD operating range of 1.71V to 3.45V, and a separate digital IO supply, VDDIO from 1.71V to 3.45V.

Communication with all registers of the device is performed using either I<sup>2</sup>C at 400 kHz or SPI at 10M Hz.

By leveraging its patented and volume-proven CMOS-MEMS fabrication platform, which integrates MEMS wafers with companion CMOS electronics through wafer-level bonding, InvenSense has driven the package size down to a footprint and thickness of 3 mm x 3 mm x 0.75 mm (24-pin LGA), to provide a very small yet high performance low cost package. The device provides high robustness by supporting 20,000g shock reliability.

### 1.3 APPLICATIONS

- Drones
- Wearable Sensors

## 2 FEATURES

### 2.1 GYROSCOPE FEATURES

The triple-axis MEMS gyroscope in the MPU-6886 includes a wide range of features:

- Digital-output X-, Y-, and Z-axis angular rate sensors (gyroscopes) with a user-programmable full-scale range of  $\pm 250$  dps,  $\pm 500$  dps,  $\pm 1000$  dps, and  $\pm 2000$  dps and integrated 16-bit ADCs
- Digitally-programmable low-pass filter
- Low-power gyroscope operation
- Factory calibrated sensitivity scale factor
- Self-test

### 2.2 ACCELEROMETER FEATURES

The triple-axis MEMS accelerometer in MPU-6886 includes a wide range of features:

- Digital-output X-, Y-, and Z-axis accelerometer with a programmable full scale range of  $\pm 2g$ ,  $\pm 4g$ ,  $\pm 8g$  and  $\pm 16g$  and integrated 16-bit ADCs
- User-programmable interrupts
- Wake-on-motion interrupt for low power operation of applications processor
- Self-test

### 2.3 ADDITIONAL FEATURES

The MPU-6886 includes the following additional features:

- Smallest and thinnest LGA package: 3 mm x 3 mm x 0.75 mm (24-pin LGA)
- Minimal cross-axis sensitivity between the accelerometer and gyroscope axes
- 1 kB FIFO buffer enables the applications processor to read the data in bursts
- Digital-output temperature sensor
- User-programmable digital filters for gyroscope, accelerometer, and temp sensor
- 20,000g shock tolerant
- 400 kHz Fast Mode I<sup>2</sup>C for communicating with all registers
- 10 MHz SPI serial interface for communicating with all registers
- MEMS structure hermetically sealed and bonded at wafer level
- RoHS and Green compliant



### 3 ELECTRICAL CHARACTERISTICS

#### 3.1 GYROSCOPE SPECIFICATIONS

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
<b>GYROSCOPE SENSITIVITY</b>						
Full-Scale Range	FS_SEL=0		±250		dps	3
	FS_SEL=1		±500		dps	3
	FS_SEL=2		±1000		dps	3
	FS_SEL=3		±2000		dps	3
Gyroscope ADC Word Length			16		bits	3
Sensitivity Scale Factor	FS_SEL=0		131		LSB/(dps)	3
	FS_SEL=1		65.5		LSB/(dps)	3
	FS_SEL=2		32.8		LSB/(dps)	3
	FS_SEL=3		16.4		LSB/(dps)	3
Sensitivity Scale Factor Initial Tolerance	25°C	-1		+1	%	1
Sensitivity Scale Factor Variation Over Temperature	-40°C to +85°C	-2.5		+2.5	%	1
Nonlinearity	Best fit straight line; 25°C	-0.2	±0.1	+0.2	%	1
Cross-Axis Sensitivity		-4.5	±1	+4.5	%	1
<b>ZERO-RATE OUTPUT (ZRO)</b>						
Initial ZRO Tolerance	25°C	-10	±1	+10	dps	1
ZRO Variation vs. Temperature	-40°C to +85°C	-0.05	±0.01	+0.05	dps/°C	1
<b>OTHER PARAMETERS</b>						
Rate Noise Spectral Density	@ 10 Hz		0.004	0.01	dps/√Hz	1, 4
Total RMS Noise	Bandwidth = 100 Hz		0.04	0.1	dps-rms	1, 4
Gyroscope Mechanical Frequencies		25	27	29	KHz	2
Low Pass Filter Response	Programmable Range	5		250	Hz	3
Gyroscope Start-Up Time	Time from gyro enable to gyro drive ready		35	100	ms	1
Output Data Rate	Low-Noise mode	3.91		8000	Hz	3
	Low Power Mode	3.91		333.33	Hz	3

**Table 1. Gyroscope Specifications**

**NOTES:**

1. Derived from validation or characterization of parts, not guaranteed in production.
2. Tested in production.
3. Guaranteed by design.
4. Noise specifications shown are for low-noise mode.

### 3.2 ACCELEROMETER SPECIFICATIONS

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES	
<b>ACCELEROMETER SENSITIVITY</b>							
Full-Scale Range	AFS_SEL=0		±2		g	2	
	AFS_SEL=1		±4		g	2	
	AFS_SEL=2		±8		g	2	
	AFS_SEL=3		±16		g	2	
ADC Word Length	Output in two's complement format		16		bits	2	
Sensitivity Scale Factor	AFS_SEL=0		16,384		LSB/g	2	
	AFS_SEL=1		8,192		LSB/g	2	
	AFS_SEL=2		4,096		LSB/g	2	
	AFS_SEL=3		2,048		LSB/g	2	
Sensitivity Scale Factor Initial Tolerance	Component-level	-1		+1	%	1	
Sensitivity Change vs. Temperature	-40°C to +85°C	-2		+2	%	1	
Nonlinearity	Best Fit Straight Line	1	±0.3	+1	%	1	
Cross-Axis Sensitivity		-4.5	±1	+4.5	%	1	
<b>ZERO-G OUTPUT</b>							
Initial Tolerance	Component-level, all axes		-65	±25	+65	mg	1
	Board-level, all axes		-100	±40	+100	mg	1
Zero-G Level Change vs. Temperature	-40°C to +85°C	X and Y axes	-0.75	±0.5	+0.75	mg/°C	1
		Z axis	-1.2	±1	+1.2	mg/°C	1
<b>OTHER PARAMETERS</b>							
Power Spectral Density	@ 10 Hz		100	170	μg/√Hz	1, 3	
RMS Noise	Bandwidth = 100 Hz		1.0	1.7	mg-rms	1, 3	
Low-Pass Filter Response	Programmable Range	5		218	Hz	2	
Accelerometer Startup Time	From sleep mode to valid data		10	20	ms	2	
Output Data Rate	Low-Noise mode	3.91		4000	Hz	2	
	Low Power Mode	3.91		500	Hz		

**Table 2. Accelerometer Specifications**

**NOTES:**

1. Derived from validation or characterization of parts, not guaranteed in production.
2. Guaranteed by design.
3. Noise specifications shown are for low-noise mode.

### 3.3 ELECTRICAL SPECIFICATIONS

#### D.C. Electrical Characteristics

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
<b>SUPPLY VOLTAGES</b>						
VDD		1.71	1.8	3.45	V	1
VDDIO		1.71	1.8	3.45	V	1
<b>SUPPLY CURRENTS</b>						
Low-Noise Mode	6-Axis Gyroscope + Accelerometer		2.79	3.0	mA	1
	3-Axis Accelerometer		321	370	μA	1
	3-Axis Gyroscope		2.55	2.8	mA	1
Accelerometer Low -Power Mode (Gyroscope disabled)	100Hz ODR, 1x averaging		40	45	μA	1
Gyroscope Low-Power Mode (Accelerometer disabled)	100Hz ODR, 1x averaging		1.08	1.2	mA	1
6-Axis Low-Power Mode (Gyroscope Low-Power Mode; Accelerometer Low-Noise Mode)	100Hz ODR, 1x averaging		1.33	1.45	mA	1
Full-Chip Sleep Mode	At 25°C		6	10	μA	1
<b>TEMPERATURE RANGE</b>						
Specified Temperature Range	Performance parameters are not applicable beyond Specified Temperature Range	-40		+85	°C	1

**Table 3. D.C. Electrical Characteristics**

**NOTES:**

1. Target spec. Subject to update.
2. Derived from validation or characterization of parts, not guaranteed in production.

**A.C. Electrical Characteristics**

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
<b>SUPPLIES</b>						
Supply Ramp Time	Monotonic ramp. Ramp rate is 10% to 90% of the final value	0.01		3	ms	1
Power Supply Noise			10		mV peak-peak	1
<b>TEMPERATURE SENSOR</b>						
Operating Range	Ambient	-40		85	°C	1
25°C Output			0		LSB	3
ADC Resolution			16		bits	2
ODR	Without Filter		8000		Hz	2
	With Filter	3.91		1000	Hz	2
Room Temperature Offset	25°C	-15		15	°C	3
Stabilization Time				14000	µs	2
Sensitivity	Untrimmed		326.8		LSB/°C	1
Sensitivity Error		-2.5		+2.5	%	1
<b>I<sup>2</sup>C ADDRESS</b>						
I <sup>2</sup> C ADDRESS	SA0 = 0 SA0 = 1		1101000 1101001			
<b>DIGITAL INPUTS (FSYNC, SA0, SPC, SDI, CS)</b>						
V <sub>IH</sub> , High Level Input Voltage		0.7*VDDIO			V	1
V <sub>IL</sub> , Low Level Input Voltage				0.3*VDDIO	V	
C <sub>I</sub> , Input Capacitance			< 10		pF	
<b>DIGITAL OUTPUT (SDO, INT, DRDY)</b>						
V <sub>OH</sub> , High Level Output Voltage	R <sub>LOAD</sub> =1 MΩ;	0.9*VDDIO			V	1
V <sub>OL</sub> , LOW-Level Output Voltage	R <sub>LOAD</sub> =1 MΩ;			0.1*VDDIO	V	
V <sub>OL,INT</sub> , INT Low-Level Output Voltage	OPEN=1, 0.3 mA sink Current			0.1	V	
Output Leakage Current	OPEN=1		100		nA	
t <sub>INT</sub> , INT Pulse Width	LATCH_INT_EN=0		50		µs	
<b>I<sup>2</sup>C I/O (SCL, SDA)</b>						
V <sub>IL</sub> , LOW Level Input Voltage		-0.5V		0.3*VDDIO	V	1
V <sub>IH</sub> , HIGH-Level Input Voltage		0.7*VDDIO		VDDIO + 0.5V	V	
V <sub>hys</sub> , Hysteresis			0.1*VDDIO		V	
V <sub>OL</sub> , LOW-Level Output Voltage	3 mA sink current	0		0.4	V	
I <sub>OL</sub> , LOW-Level Output Current	V <sub>OL</sub> =0.4V V <sub>OL</sub> =0.6V		3 6		mA mA	
Output Leakage Current			100		nA	
t <sub>of</sub> , Output Fall Time from V <sub>IHmax</sub> to V <sub>ILmax</sub>	C <sub>b</sub> bus capacitance in pf	20+0.1C <sub>b</sub>		300	ns	
<b>INTERNAL CLOCK SOURCE</b>						
Sample Rate	FCHOICE_B=1,2,3; SMPLRT_DIV=0		32		kHz	2
	FCHOICE_B=0; DLPCFG=0 or 7 SMPLRT_DIV=0		8		kHz	2

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
	FCHOICE_B=0; DLPFCFG=1,2,3,4,5,6; SMPLRT_DIV=0		1		kHz	2
Clock Frequency Initial Tolerance	CLK_SEL=0, 6 or gyro inactive; 25°C	-3		+3	%	1
	CLK_SEL=1,2,3,4,5 and gyro active; 25°C	-1		+1	%	1
Frequency Variation over Temperature	CLK_SEL=0,6 or gyro inactive. (-40°C to +85°C)			±2	%	1
	CLK_SEL=1,2,3,4,5 and gyro active			±2	%	1

**Table 4. A.C. Electrical Characteristics**

**NOTES:**

1. Derived from validation or characterization of parts, not guaranteed in production.
2. Guaranteed by design.
3. Production tested.

**Other Electrical Specifications**

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
<b>SERIAL INTERFACE</b>						
SPI Operating Frequency, All Registers Read/Write	Low Speed Characterization	100	100 ±10%		kHz	1,3
	High Speed Characterization	0.2	1	10	MHz	1, 2, 3
SPI Modes			0 and 3			
I <sup>2</sup> C Operating Frequency	All registers, Fast-mode	100		400	kHz	1
	All registers, Standard-mode			100	kHz	1

**Table 5. Other Electrical Specifications**

**NOTES:**

1. Derived from validation or characterization of parts, not guaranteed in production.
2. SPI clock duty cycle between 45% and 55% should be used for 10 MHz operation.
3. Minimum SPI/I<sup>2</sup>C clock rate is dependent on ODR. If ODR is below 4 kHz, minimum clock rate is 100 kHz. If ODR is greater than 4 kHz, minimum clock rate is 200 kHz.

### 3.4 I<sup>2</sup>C TIMING CHARACTERIZATION

Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETERS	CONDITIONS	MIN	TYPICAL	MAX	UNITS	NOTES
<b>I<sup>2</sup>C TIMING</b>						
<b>I<sup>2</sup>C FAST-MODE</b>						
f <sub>SCL</sub> , SCL Clock Frequency		100		400	kHz	1
t <sub>HD,STA</sub> , (Repeated) START Condition Hold Time		0.6			μs	1
t <sub>LOW</sub> , SCL Low Period		1.3			μs	1
t <sub>HIGH</sub> , SCL High Period		0.6			μs	1
t <sub>SU,STA</sub> , Repeated START Condition Setup Time		0.6			μs	1
t <sub>HD,DAT</sub> , SDA Data Hold Time		0			μs	1
t <sub>SU,DAT</sub> , SDA Data Setup Time		100			ns	1
t <sub>r</sub> , SDA and SCL Rise Time	C <sub>b</sub> bus cap. from 10 to 400 pF	20+0.1C <sub>b</sub>		300	ns	1
t <sub>f</sub> , SDA and SCL Fall Time	C <sub>b</sub> bus cap. from 10 to 400 pF	20+0.1C <sub>b</sub>		300	ns	1
t <sub>SU,STO</sub> , STOP Condition Setup Time		0.6			μs	1
t <sub>BUF</sub> , Bus Free Time Between STOP and START Condition		1.3			μs	1
C <sub>b</sub> , Capacitive Load for each Bus Line			< 400		pF	1
t <sub>VD,DAT</sub> , Data Valid Time				0.9	μs	1
t <sub>VD,ACK</sub> , Data Valid Acknowledge Time				0.9	μs	1

Table 6. I<sup>2</sup>C Timing Characteristics

**NOTE:**

- Based on characterization of 5 parts over temperature and voltage as mounted on evaluation board or in sockets

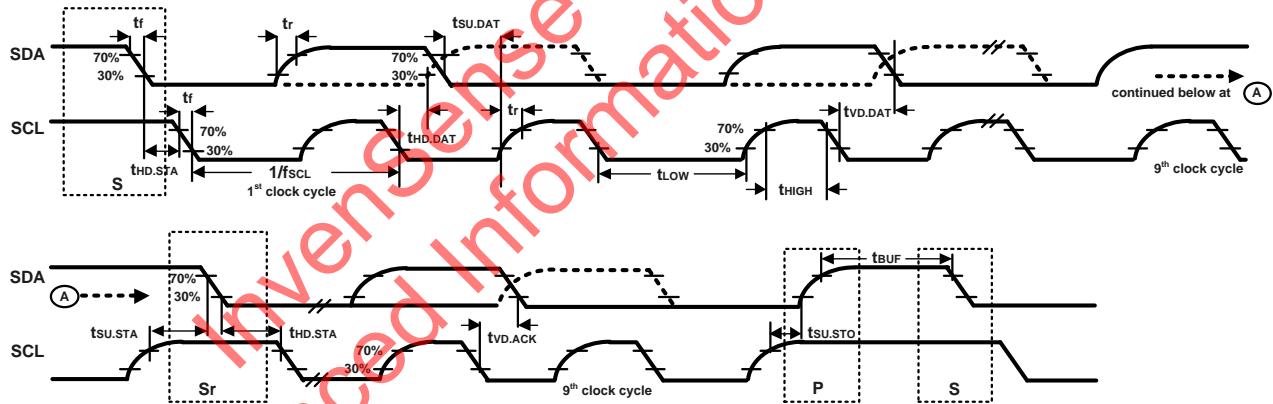


Figure 1. I<sup>2</sup>C Bus Timing Diagram

### 3.5 SPI TIMING CHARACTERIZATION

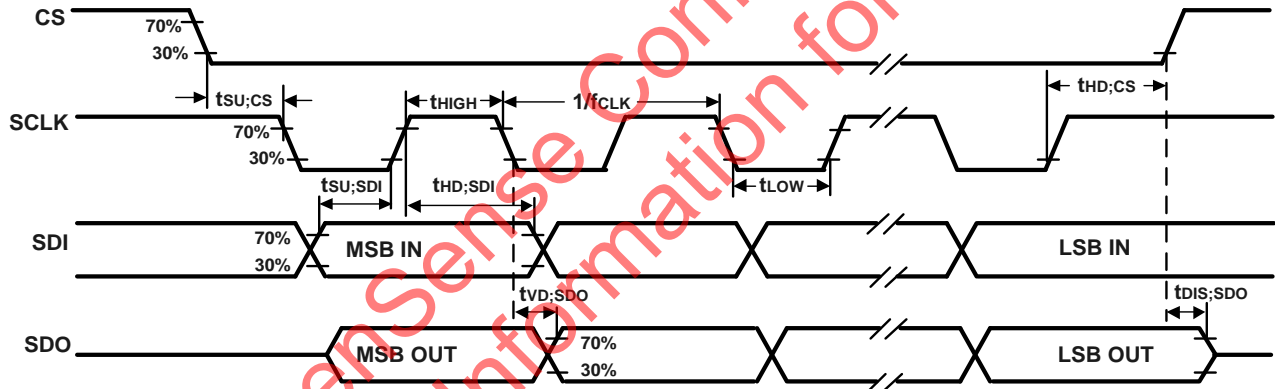
Typical Operating Circuit of section 4.2, VDD = 1.8V, VDDIO = 1.8V, T<sub>A</sub>=25°C, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
<b>SPI TIMING</b>						
f <sub>SPC</sub> , SPC Clock Frequency				10	MHz	1
t <sub>LOW</sub> , SPC Low Period		45			ns	1
t <sub>HIGH</sub> , SPC High Period		45			ns	1
t <sub>SU,CS</sub> , CS Setup Time		2			ns	1
t <sub>HD,CS</sub> , CS Hold Time		63			ns	1
t <sub>SU,SDI</sub> , SDI Setup Time		3			ns	1
t <sub>HD,SDI</sub> , SDI Hold Time		7			ns	1
t <sub>VD,SDO</sub> , SDO Valid Time	C <sub>load</sub> = 20 pF			40	ns	1
t <sub>DIS,SDO</sub> , SDO Output Disable Time				20	ns	1

**Table 7. SPI Timing Characteristics (10 MHz Operation)**

**Notes:**

1. Based on characterization of 5 parts over temperature and voltage as mounted on evaluation board or in sockets



**Figure 2. SPI Bus Timing Diagram**

### 3.6 ABSOLUTE MAXIMUM RATINGS

Stress above those listed as “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to the absolute maximum ratings conditions for extended periods may affect device reliability.

PARAMETER	RATING
Supply Voltage, VDD	-0.5V to +4V
Supply Voltage, VDDIO	-0.5V to +4V
REGOUT	-0.5V to 2V
Input Voltage Level (SA0, FSYNC, SCL, SDA)	-0.5V to VDDIO + 0.5V
Acceleration (Any Axis, unpowered)	20,000g for 0.2ms
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +125°C
Electrostatic Discharge (ESD) Protection	2kV (HBM); 250V (MM)
Latch-up	JEDEC Class II (2), 125°C ±100mA

**Table 8. Absolute Maximum Ratings**

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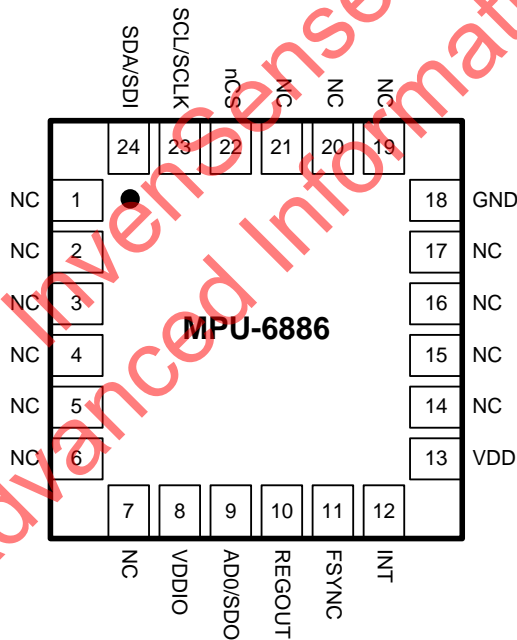
## 4 APPLICATIONS INFORMATION

### 4.1 PIN OUT DIAGRAM AND SIGNAL DESCRIPTION

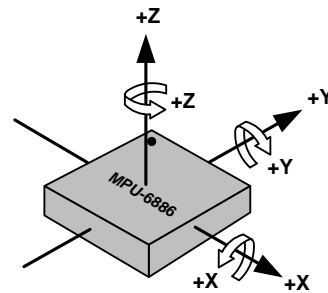
PIN NUMBER	PIN NAME
23	SCL / SCLK
24	SDA / SDI
9	AD0 / SDO
11	FSYNC / NC
19	RESV (INT/TP0)
8	VDDIO
12	INT1/DRDY/TP2
22	nCS
20	RESV (VPP)
10	REGOUT
13	VDD
18	GND
1,2,3,4,5,6,7,14,15,16,17,21	NC

**Table 9. Signal Descriptions**

**NOTE:** Power up with SCL/SPC and CS pins held low is not a supported use case. In case this power up approach is used, software reset is required using the PWR\_MGMT\_1 register, prior to initialization.



**Top View – LGA Package**  
24-pin, 3mm x 3mm x 0.75mm



**Orientation of Axes of Sensitivity and**  
**Polarity of Rotation**

**Figure 3. Pin out Diagram for MPU-6886 3.0 mm x 3.0 mm x 0.75 mm LGA**

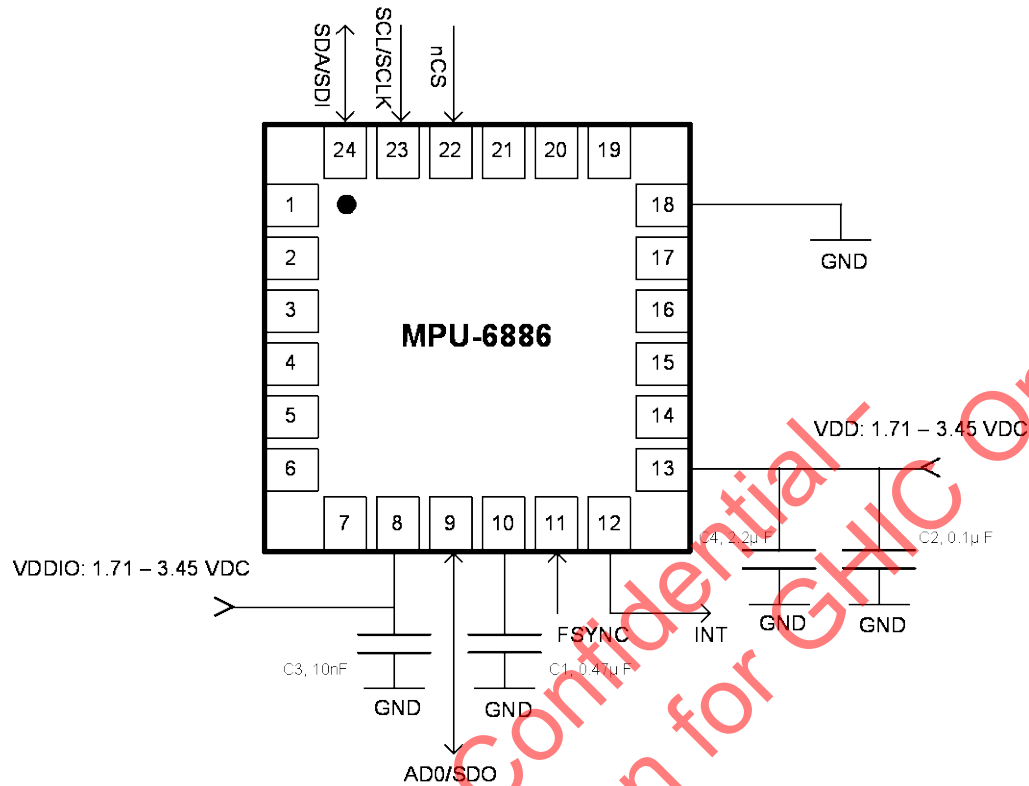


Figure 4. MPU-6886 LGA Example Application Schematic

#### 4.2 TYPICAL OPERATING CIRCUIT

I<sup>2</sup>C lines are open drain and pullup resistors (e.g. 10kΩ) are required.

#### 4.3 BILL OF MATERIALS FOR EXTERNAL COMPONENTS

COMPONENT	LABEL	SPECIFICATION	QUANTITY
REGOUT Capacitor	C1	X7R, 0.1 µF ±10%	1
VDD Bypass Capacitors	C2	X7R, 0.1 µF ±10%	1
	C4	X7R, 2.2 µF ±10%	1
VDDIO Bypass Capacitor	C3	X7R, 10 nF ±10%	1

Table 10. Bill of Materials

#### 4.4 EXPOSED DIE PAD PRECAUTIONS

InvenSense products have very low active and standby current consumption. The exposed die pad is not required for heat sinking, and should not be soldered to the PCB. Failure to adhere to this rule can induce performance changes due to package thermo-mechanical stress. There is no electrical connection between the pad and the CMOS.

#### 4.5 BLOCK DIAGRAM

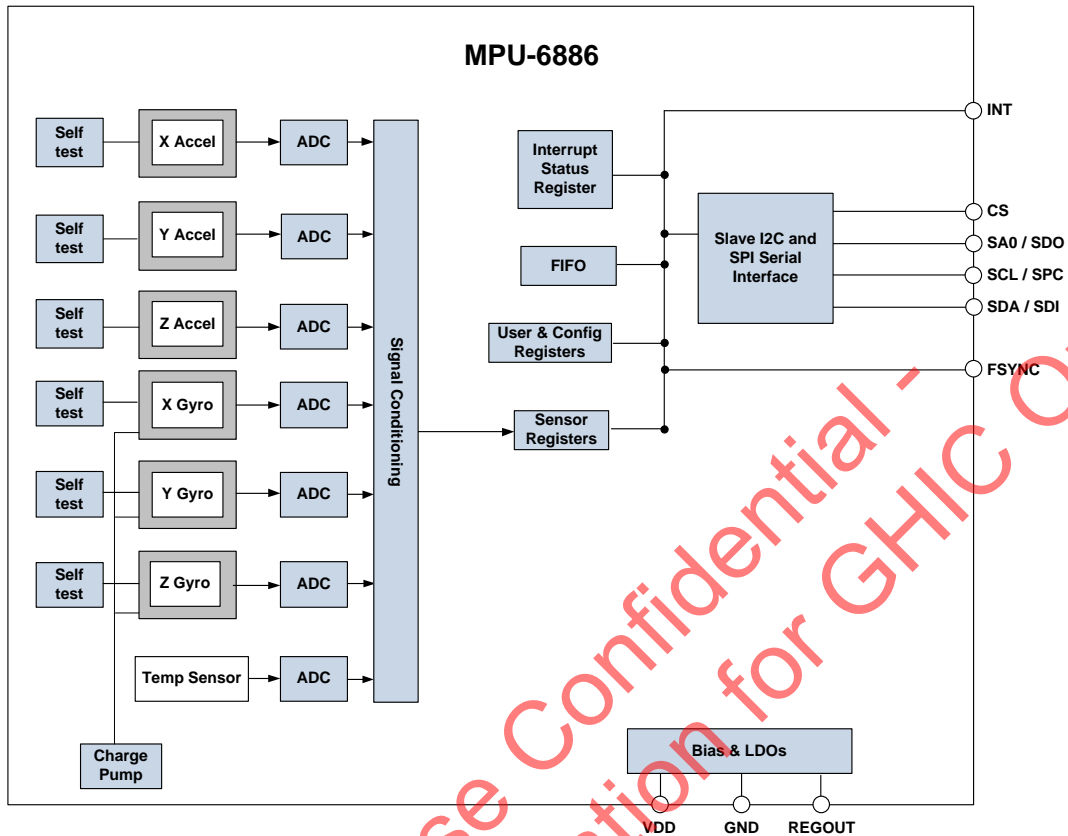


Figure 5. MPU-6886 Block Diagram

#### 4.6 OVERVIEW

The MPU-6886 is comprised of the following key blocks and functions:

- Three-axis MEMS rate gyroscope sensor with 16-bit ADCs and signal conditioning
- Three-axis MEMS accelerometer sensor with 16-bit ADCs and signal conditioning
- I<sup>2</sup>C and SPI serial communications interface
- Self-Test
- Clocking
- Sensor Data Registers
- FIFO
- Interrupts
- Digital-Output Temperature Sensor
- Bias and LDOs
- Charge Pump
- Standard Power Modes

#### 4.7 THREE-AXIS MEMS GYROSCOPE WITH 16-BIT ADCS AND SIGNAL CONDITIONING

The MPU-6886 consists of three independent vibratory MEMS rate gyroscopes, which detect rotation about the X-, Y-, and Z- Axes. When the gyros are rotated about any of the sense axes, the Coriolis Effect causes a vibration that is detected by a capacitive pickoff. The resulting signal is amplified, demodulated, and filtered to produce a voltage that is proportional to the angular rate. This voltage is digitized using individual on-chip 16-bit Analog-to-Digital Converters (ADCs) to sample each axis. The full-scale range of the gyro sensors may be digitally programmed to  $\pm 250$ ,  $\pm 500$ ,  $\pm 1000$ , or  $\pm 2000$  degrees per second (dps). The ADC sample rate is programmable from 8,000 samples per second, down to 3.9 samples per second, and user-selectable low-pass filters enable a wide range of cut-off frequencies.

#### 4.8 THREE-AXIS MEMS ACCELEROMETER WITH 16-BIT ADCS AND SIGNAL CONDITIONING

The MPU-6886's 3-Axis accelerometer uses separate proof masses for each axis. Acceleration along a particular axis induces displacement on the corresponding proof mass, and capacitive sensors detect the displacement differentially. The MPU-6886's architecture reduces the accelerometers' susceptibility to fabrication variations as well as to thermal drift. When the device is placed on a flat surface, it will measure 0g on the X- and Y-axes and +1g on the Z-axis. The accelerometers' scale factor is calibrated at the factory and is nominally independent of supply voltage. Each sensor has a dedicated sigma-delta ADC for providing digital outputs. The full scale range of the digital output can be adjusted to  $\pm 2g$ ,  $\pm 4g$ ,  $\pm 8g$ , or  $\pm 16g$ .

#### 4.9 I2C AND SPI SERIAL COMMUNICATIONS INTERFACES

The MPU-6886 communicates to a system processor using either a SPI or an I<sup>2</sup>C serial interface. The MPU-6886 always acts as a slave when communicating to the system processor. The LSB of the I<sup>2</sup>C slave address is set by pin 9 (SA0).

#### MPU-6886 Solution Using I<sup>2</sup>C Interface

In Figure 6, the system processor is an I<sup>2</sup>C master to the MPU-6886.

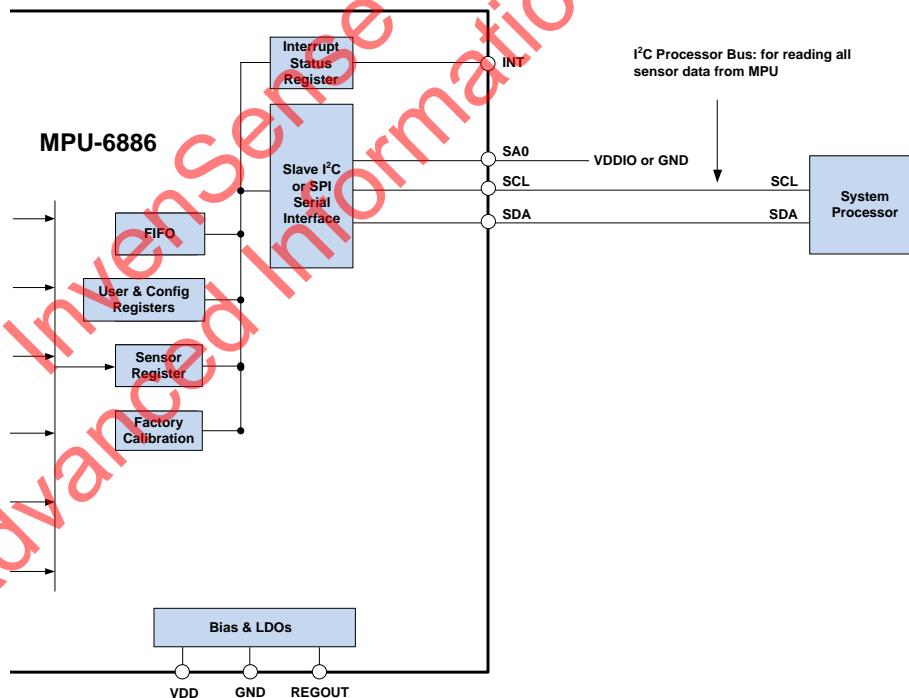


Figure 6. MPU-6886 Solution Using I<sup>2</sup>C Interface

### MPU-6886 Solution Using SPI Interface

In Figure 7, the system processor is an SPI master to the MPU-6886. Pins 23, 24, 9, and 22 are used to support the SPC, SDI, SDO, and CS signals for SPI communications.

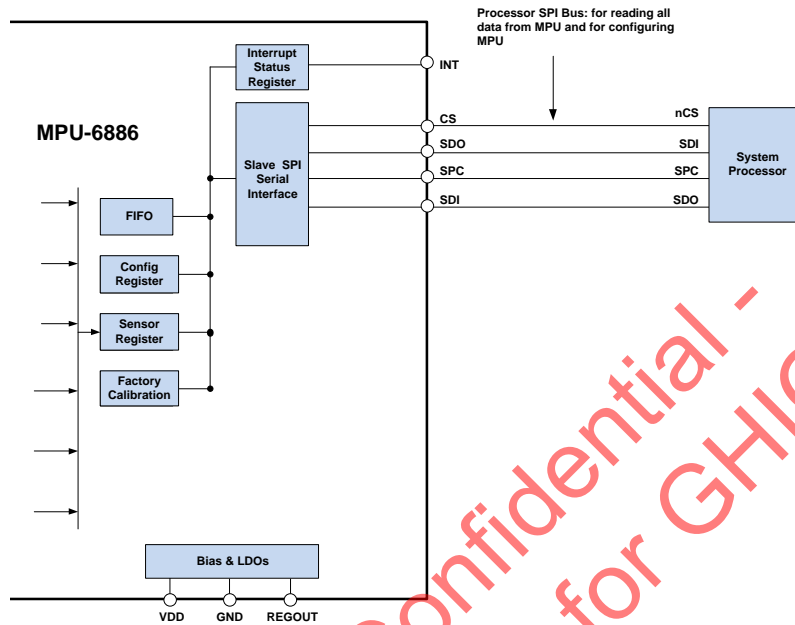


Figure 7. MPU-6886 Solution Using SPI Interface

#### 4.10 SELF-TEST

Self-test allows for the testing of the mechanical and electrical portions of the sensors. The self-test for each measurement axis can be activated by means of the gyroscope and accelerometer self-test registers (registers 27 and 28).

When the self-test is activated, the electronics cause the sensors to be actuated and produce an output signal. The output signal is used to observe the self-test response.

The self-test response is defined as follows:

$$\text{SELF-TEST RESPONSE} = \text{SENSOR OUTPUT WITH SELF-TEST ENABLED} - \text{SENSOR OUTPUT WITH SELF-TEST DISABLED}$$

The self-test response for each gyroscope axis is defined in the gyroscope specification table, while that for each accelerometer axis is defined in the accelerometer specification table.

When the value of the self-test response is within the specified min/max limits of the product specification, the part has passed self-test. When the self-test response exceeds the min/max values, the part is deemed to have failed self-test.

#### 4.11 CLOCKING

The MPU-6886 has a flexible clocking scheme, allowing a variety of internal clock sources to be used for the internal synchronous circuitry. This synchronous circuitry includes the signal conditioning and ADCs, and various control circuits and registers. An on-chip PLL provides flexibility in the allowable inputs for generating this clock.

Allowable internal sources for generating the internal clock are:

- a) An internal relaxation oscillator
- b) Auto-select between internal relaxation oscillator and gyroscope MEMS oscillator to use the best available source

The only setting supporting specified performance in all modes is option b). It is recommended that option b) be used.

#### 4.12 SENSOR DATA REGISTERS

The sensor data registers contain the latest gyroscope, accelerometer, and temperature measurement data. They are read-only registers, and are accessed via the serial interface. Data from these registers may be read anytime.

#### 4.13 FIFO

The MPU-6886 contains a 1 kB FIFO register that is accessible via the Serial Interface. The FIFO configuration register determines which data is written into the FIFO. Possible choices include gyro data, accelerometer data, temperature readings, and FSYNC input. A FIFO counter keeps track of how many bytes of valid data are contained in the FIFO. The FIFO register supports burst reads. The interrupt function may be used to determine when new data is available.

The MPU-6886 allows FIFO read in low-power accelerometer mode.

#### 4.14 INTERRUPTS

Interrupt functionality is configured via the Interrupt Configuration register. Items that are configurable include the INT and DRDY pins configuration, the interrupt latching and clearing method, and triggers for the interrupt. Items that can trigger an interrupt are (1) Clock generator locked to new reference oscillator (used when switching clock sources); (2) new data is available to be read (from the FIFO and Data registers); (3) accelerometer event interrupts; (4) FIFO overflow. The interrupt status can be read from the Interrupt Status register.

#### 4.15 DIGITAL-OUTPUT TEMPERATURE SENSOR

An on-chip temperature sensor and ADC are used to measure the MPU-6886 die temperature. The readings from the ADC can be read from the FIFO or the Sensor Data registers.

#### 4.16 BIAS AND LDOS

The bias and LDO section generates the internal supply and the reference voltages and currents required by the MPU-6886. Its two inputs are an unregulated VDD and a VDDIO logic reference supply voltage. The LDO output is bypassed by a capacitor at REGOUT. For further details on the capacitor, please refer to the Bill of Materials for External Components.

#### 4.17 CHARGE PUMP

An on-chip charge pump generates the high voltage required for the MEMS oscillator.

#### 4.18 STANDARD POWER MODES

The following table lists the user-accessible power modes for MPU-6886.

MODE	NAME	GYRO	ACCEL
1	Sleep Mode	Off	Off
2	Standby Mode	Drive On	Off
3	Accelerometer Low-Power Mode	Off	Duty-Cycled
4	Accelerometer Low-Noise Mode	Off	On
5	Gyroscope Low-Power Mode	Duty-Cycled	Off
6	Gyroscope Low-Noise Mode	On	Off
7	6-Axis Low-Noise Mode	On	On
8	6-Axis Low-Power Mode	Duty-Cycled	On

**Table 11. Standard Power Modes for MPU-6886**

**NOTES:**

1. Power consumption for individual modes can be found in D.C. Electrical Characteristics.

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## 5 PROGRAMMABLE INTERRUPTS

The MPU-6886 has a programmable interrupt system which can generate an interrupt signal on the INT and DRDY pins. Status flags indicate the source of an interrupt. Interrupt sources may be enabled and disabled individually.

INTERRUPT NAME	MODULE
Motion Detection	Motion
FIFO Overflow	FIFO
Data Ready	Sensor Registers

**Table 12. Table of Interrupt Sources**

For information regarding the interrupt enable/disable registers and flag registers, please refer to sections 11 and 12 of this document. Some interrupt sources are explained below.

### 5.1 WAKE-ON-MOTION INTERRUPT

The MPU-6886 provides motion detection capability. A qualifying motion sample is one where the high passed sample from any axis has an absolute value exceeding a user-programmable threshold. The following steps explain how to configure the Wake-on-Motion Interrupt.

**Step 1: Ensure that Accelerometer is running**

- In PWR\_MGMT\_1 register (0x6B) set CYCLE = 0, SLEEP = 0, and GYRO\_STANDBY = 0
- In PWR\_MGMT\_2 register (0x6C) set STBY\_XA = STBY\_YA = STBY\_ZA = 0, and STBY\_XG = STBY\_YG = STBY\_ZG = 1

**Step 2: Set Accelerometer LPF bandwidth to 218.1 Hz**

- In ACEEL\_CONFIG2 register (0x1D) set ACCEL\_FCHOICE\_B = 0 and A\_DLPF\_CFG[2:0] = 1 (b001)

**Step 3: Enable Motion Interrupt**

- In INT\_ENABLE register (0x38) set WOM\_INT\_EN = 111 to enable motion interrupt

**Step 4: Set Motion Threshold**

- Set the motion threshold in ACCEL\_WOM\_THR register (0x1F)

**Step 5: Enable Accelerometer Hardware Intelligence**

- In ACCEL\_INTEL\_CTRL register (0x69) set ACCEL\_INTEL\_EN = ACCEL\_INTEL\_MODE = 1; Ensure that bit 0 is set to 0

**Step 7: Set Frequency of Wake-Up**

- In SMPLRT\_DIV register (0x19) set SMPLRT\_DIV[7:0] = 3.9 Hz – 500 Hz

**Step 8: Enable Cycle Mode (Accelerometer Low-Power Mode)**

- In PWR\_MGMT\_1 register (0x6B) set CYCLE = 1



## 6 DIGITAL INTERFACE

### 6.1 I<sup>2</sup>C AND SPI SERIAL INTERFACES

The internal registers and memory of the MPU-6886 can be accessed using either I<sup>2</sup>C at 400 kHz or SPI at 10 MHz. SPI operates in four-wire mode.

PIN NUMBER	PIN NAME	PIN DESCRIPTION
23	SCL / SPC	I <sup>2</sup> C serial clock (SCL); SPI serial clock (SPC)
24	SDA / SDI	I <sup>2</sup> C serial data (SDA); SPI serial data input (SDI)
9	SA0 / SDO	I <sup>2</sup> C Slave Address LSB (SA0); SPI serial data output (SDO)
22	CS	Chip select (0 = SPI mode)

Table 13. Serial Interface

### 6.2 I<sup>2</sup>C INTERFACE

I<sup>2</sup>C is a two-wire interface comprised of the signals serial data (SDA) and serial clock (SCL). In general, the lines are open-drain and bi-directional. In a generalized I<sup>2</sup>C interface implementation, attached devices can be a master or a slave. The master device puts the slave address on the bus, and the slave device with the matching address acknowledges the master.

The MPU-6886 always operates as a slave device when communicating to the system processor, which thus acts as the master. SDA and SCL lines typically need pull-up resistors to VDD. The maximum bus speed is 400 kHz.

The slave address of the MPU-6886 is b110100X which is 7 bits long. The LSB bit of the 7-bit address is determined by the logic level on pin SA0. This allows two MPU-6886s to be connected to the same I<sup>2</sup>C bus. When used in this configuration, the address of one of the devices should be b1101000 (pin SA0 is logic low) and the address of the other should be b1101001 (pin SA0 is logic high).

### 6.3 I<sup>2</sup>C COMMUNICATIONS PROTOCOL

#### START (S) and STOP (P) Conditions

Communication on the I<sup>2</sup>C bus starts when the master puts the START condition (S) on the bus, which is defined as a HIGH-to-LOW transition of the SDA line while SCL line is HIGH (see figure below). The bus is considered to be busy until the master puts a STOP condition (P) on the bus, which is defined as a LOW to HIGH transition on the SDA line while SCL is HIGH (see figure below).

Additionally, the bus remains busy if a repeated START (Sr) is generated instead of a STOP condition.

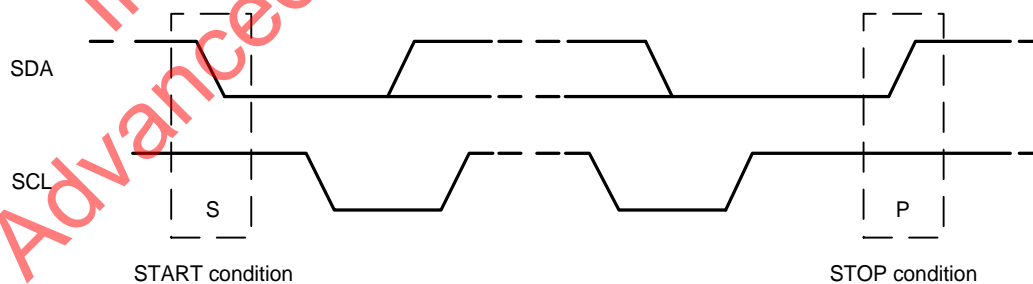
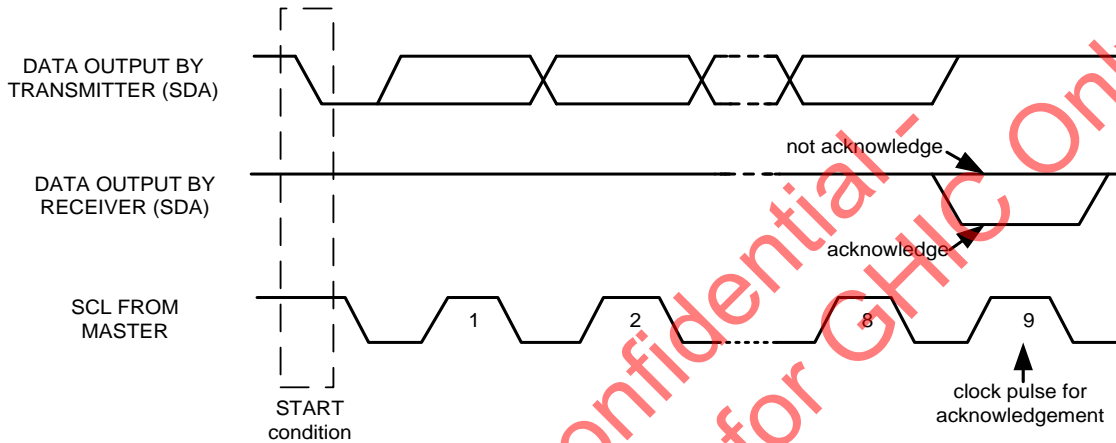


Figure 8. START and STOP Conditions

*Data Format / Acknowledge*

I<sup>2</sup>C data bytes are defined to be 8-bits long. There is no restriction to the number of bytes transmitted per data transfer. Each byte transferred must be followed by an acknowledge (ACK) signal. The clock for the acknowledge signal is generated by the master, while the receiver generates the actual acknowledge signal by pulling down SDA and holding it low during the HIGH portion of the acknowledge clock pulse.

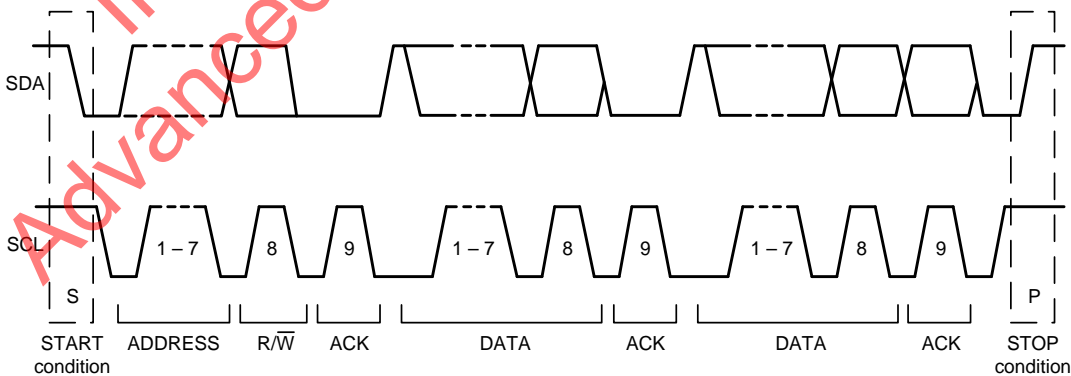
If a slave is busy and cannot transmit or receive another byte of data until some other task has been performed, it can hold SCL LOW, thus forcing the master into a wait state. Normal data transfer resumes when the slave is ready, and releases the clock line (refer to the following figure).



**Figure 9. Acknowledge on the I<sup>2</sup>C Bus**

*Communications*

After beginning communications with the START condition (S), the master sends a 7-bit slave address followed by an 8<sup>th</sup> bit, the read/write bit. The read/write bit indicates whether the master is receiving data from or is writing to the slave device. Then, the master releases the SDA line and waits for the acknowledge signal (ACK) from the slave device. Each byte transferred must be followed by an acknowledge bit. To acknowledge, the slave device pulls the SDA line LOW and keeps it LOW for the high period of the SCL line. Data transmission is always terminated by the master with a STOP condition (P), thus freeing the communications line. However, the master can generate a repeated START condition (Sr), and address another slave without first generating a STOP condition (P). A LOW to HIGH transition on the SDA line while SCL is HIGH defines the stop condition. All SDA changes should take place when SCL is low, with the exception of start and stop conditions.



**Figure 10. Complete I<sup>2</sup>C Data Transfer**

To write the internal MPU-6886 registers, the master transmits the start condition (S), followed by the I<sup>2</sup>C address and the write bit (0). At the 9<sup>th</sup> clock cycle (when the clock is high), the MPU-6886 acknowledges the transfer. Then the master puts the register address (RA) on the bus. After the MPU-6886 acknowledges the reception of the register address, the master puts the register data onto the bus. This is followed by the ACK signal, and data transfer may be concluded by the stop condition (P). To write multiple bytes after the last ACK signal, the master can continue outputting data rather than transmitting a stop signal. In this case, the MPU-6886 automatically increments the register address and loads the data to the appropriate register. The following figures show single and two-byte write sequences.

*Single-Byte Write Sequence*

Master	S	AD+W		RA		DATA		P
Slave			ACK		ACK		ACK	

*Burst Write Sequence*

Master	S	AD+W		RA		DATA		DATA		P
Slave			ACK		ACK		ACK		ACK	

To read the internal MPU-6886 registers, the master sends a start condition, followed by the I<sup>2</sup>C address and a write bit, and then the register address that is going to be read. Upon receiving the ACK signal from the MPU-6886, the master transmits a start signal followed by the slave address and read bit. As a result, the MPU-6886 sends an ACK signal and the data. The communication ends with a not acknowledge (NACK) signal and a stop bit from master. The NACK condition is defined such that the SDA line remains high at the 9<sup>th</sup> clock cycle. The following figures show single and two-byte read sequences.

*Single-Byte Read Sequence*

Master	S	AD+W		RA		S	AD+R		NACK	P
Slave			ACK		ACK			ACK	DATA	

*Burst Read Sequence*

Master	S	AD+W		RA		S	AD+R			ACK		NACK	P
Slave			ACK		ACK			ACK	DATA		DATA		

**6.4 I<sup>2</sup>C TERMS**

SIGNAL	DESCRIPTION
S	Start Condition: SDA goes from high to low while SCL is high
AD	Slave I <sup>2</sup> C address
W	Write bit (0)
R	Read bit (1)
ACK	Acknowledge: SDA line is low while the SCL line is high at the 9 <sup>th</sup> clock cycle
NACK	Not-Acknowledge: SDA line stays high at the 9 <sup>th</sup> clock cycle
RA	MPU-6886 internal register address
DATA	Transmit or received data
P	Stop condition: SDA going from low to high while SCL is high

**Table 14. I<sup>2</sup>C Terms**

## 6.5 SPI INTERFACE

SPI is a 4-wire synchronous serial interface that uses two control lines and two data lines. The MPU-6886 always operates as a Slave device during standard Master-Slave SPI operation.

With respect to the Master, the Serial Clock output (SPC), the Serial Data Output (SDO) and the Serial Data Input (SDI) are shared among the Slave devices. Each SPI slave device requires its own Chip Select (CS) line from the master.

CS goes low (active) at the start of transmission and goes back high (inactive) at the end. Only one CS line is active at a time, ensuring that only one slave is selected at any given time. The CS lines of the non-selected slave devices are held high, causing their SDO lines to remain in a high-impedance (high-z) state so that they do not interfere with any active devices.

### SPI Operational Features

1. Data is delivered MSB first and LSB last
2. Data is latched on the rising edge of SPC
3. Data should be transitioned on the falling edge of SPC
4. The maximum frequency of SPC is 10MHz
5. SPI read and write operations are completed in 16 or more clock cycles (two or more bytes). The first byte contains the SPI Address, and the following byte(s) contain(s) the SPI data. The first bit of the first byte contains the Read/Write bit and indicates the Read (1) or Write (0) operation. The following 7 bits contain the Register Address. In cases of multiple-byte Read/Writes, data is two or more bytes:

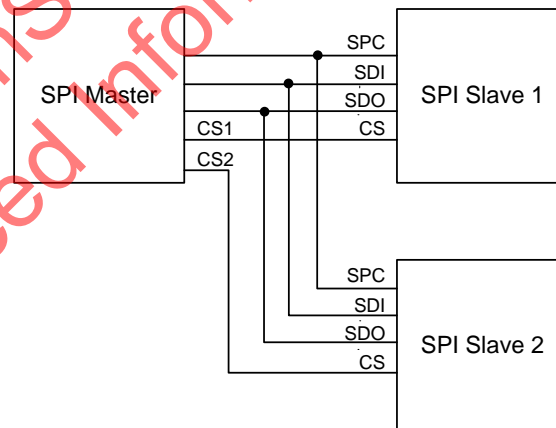
#### SPI Address format

MSB							LSB
R/W	A6	A5	A4	A3	A2	A1	A0

#### SPI Data format

MSB							LSB
D7	D6	D5	D4	D3	D2	D1	D0

6. Supports Single or Burst Read/Writes.



**Figure 11. Typical SPI Master/Slave Configuration**

## 7 REGISTER MAP

The following table lists the register map for the MPU-6886. Note that all registers are accessible in all modes of device operation.

ADDR (HEX)	ADDR (DEC.)	REGISTER NAME	SERIAL I/F	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0	
04	04	XG_OFFS_TC_H	READ/ WRITE	XG_OFFS_LP[5:0]						XG_OFFS_TC_H [9:8]		
05	05	XG_OFFS_TC_L	READ/ WRITE	XG_OFFS_TC_L [7:0]								
07	07	YG_OFFS_TC_H	READ/ WRITE	YG_OFFS_LP[5:0]						YG_OFFS_TC_H [9:8]		
08	08	YG_OFFS_TC_L	READ/ WRITE	YG_OFFS_TC_L [7:0]								
0A	10	ZG_OFFS_TC_H	READ/ WRITE	ZG_OFFS_LP[5:0]						ZG_OFFS_TC_H [9:8]		
0B	11	ZG_OFFS_TC_L	READ/ WRITE	ZG_OFFS_TC_L [7:0]								
0D	13	SELF_TEST_X_ACCEL	READ/ WRITE	XA_ST_DATA[7:0]								
0E	14	SELF_TEST_Y_ACCEL	READ/ WRITE	YA_ST_DATA[7:0]								
0F	15	SELF_TEST_Z_ACCEL	READ/ WRITE	ZA_ST_DATA[7:0]								
13	19	XG_OFFS_USRH	READ/ WRITE	X_OFFS_USR [15:8]								
14	20	XG_OFFS_USRL	READ/ WRITE	X_OFFS_USR [7:0]								
15	21	YG_OFFS_USRH	READ/ WRITE	Y_OFFS_USR [15:8]								
16	22	YG_OFFS_USRL	READ/ WRITE	Y_OFFS_USR [7:0]								
17	23	ZG_OFFS_USRH	READ/ WRITE	Z_OFFS_USR [15:8]								
18	24	ZG_OFFS_USRL	READ/ WRITE	Z_OFFS_USR [7:0]								
19	25	SMP_LRT_DIV	READ/ WRITE	SMP_LRT_DIV[7:0]								
1A	26	CONFIG	READ/ WRITE	-	FIFO_MODE	EXT_SYNC_SET[2:0]		DLPF_CFG[2:0]				
1B	27	GYRO_CONFIG	READ/ WRITE	XG_ST	YG_ST	ZG_ST	FS_SEL [1:0]		-	FCHOICE_B[1:0]		
1C	28	ACCEL_CONFIG	READ/ WRITE	XA_ST	YA_ST	ZA_ST	ACCEL_FS_SEL[1:0]		-			
1D	29	ACCEL_CONFIG 2	READ/ WRITE	-		DEC2_CFG		ACCEL_FCHOICE_B	A_DLPF_CFG			
1E	30	LP_MODE_CFG	READ/ WRITE	GYRO_CYCLE	G_AVG_CFG[2:0]			-				
20	32	ACCEL_WOM_X_THR	READ/ WRITE	WOM_X_TH[7:0]								
21	33	ACCEL_WOM_Y_THR	READ/ WRITE	WOM_Y_TH[7:0]								
22	34	ACCEL_WOM_Z_THR	READ/ WRITE	WOM_Z_TH[7:0]								
23	35	FIFO_EN	READ/ WRITE	-			GYRO_FIFO_EN	ACCEL_FIFO_EN	-			
36	54	FSYNC_INT	READ to CLEAR	FSYNC_INT	-							

ADDR (HEX)	ADDR (DEC.)	REGISTER NAME	SERIAL I/F	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0	
37	55	INT_PIN_CFG	READ/WRITE	INT_LEVEL	INT_OPEN	LATCH_INT_EN	INT_RD_CLEAR	FSYNC_INT_LEVEL	FSYNC_INT_MODE_EN	-		
38	56	INT_ENABLE	READ/WRITE	WOM_X_INT_EN	WOM_Y_INT_EN	WOM_Z_INT_EN	FIFO_OFLOW_EN	-	GDRIVE_INT_EN	-	DATA_RDY_INT_EN	
39	57	FIFO_WM_INT_STATUS	READ to CLEAR	-	FIFO_WM_INT	-						
3A	58	INT_STATUS	READ to CLEAR	WOM_X_INT	WOM_Y_INT	WOM_Z_INT	FIFO_OFLOW_INT	-	GDRIVE_INT	-	DATA_RDY_INT	
3B	59	ACCEL_XOUT_H	READ	ACCEL_XOUT[15:8]								
3C	60	ACCEL_XOUT_L	READ	ACCEL_XOUT[7:0]								
3D	61	ACCEL_YOUT_H	READ	ACCEL_YOUT[15:8]								
3E	62	ACCEL_YOUT_L	READ	ACCEL_YOUT[7:0]								
3F	63	ACCEL_ZOUT_H	READ	ACCEL_ZOUT[15:8]								
40	64	ACCEL_ZOUT_L	READ	ACCEL_ZOUT[7:0]								
41	65	TEMP_OUT_H	READ	TEMP_OUT[15:8]								
42	66	TEMP_OUT_L	READ	TEMP_OUT[7:0]								
43	67	GYRO_XOUT_H	READ	GYRO_XOUT[15:8]								
44	68	GYRO_XOUT_L	READ	GYRO_XOUT[7:0]								
45	69	GYRO_YOUT_H	READ	GYRO_YOUT[15:8]								
46	70	GYRO_YOUT_L	READ	GYRO_YOUT[7:0]								
47	71	GYRO_ZOUT_H	READ	GYRO_ZOUT[15:8]								
48	72	GYRO_ZOUT_L	READ	GYRO_ZOUT[7:0]								
50	80	SELF_TEST_X_GYRO	READ/WRITE	XG_ST_DATA[7:0]								
51	81	SELF_TEST_Y_GYRO	READ/WRITE	YG_ST_DATA[7:0]								
52	82	SELF_TEST_Z_GYRO	READ/WRITE	ZG_ST_DATA[7:0]								
53	83	E_ID0	READ/WRITE	ENGINEERING_ID0[7:0]								
54	84	E_ID1	READ/WRITE	ENGINEERING_ID1[7:0]								
55	85	E_ID2	READ/WRITE	ENGINEERING_ID2[7:0]								
56	86	E_ID3	READ/WRITE	ENGINEERING_ID3[7:0]								
57	87	E_ID4	READ/WRITE	ENGINEERING_ID4[7:0]								
58	88	E_ID5	READ/WRITE	ENGINEERING_ID5[7:0]								
59	89	E_ID6	READ/WRITE	ENGINEERING_ID6[7:0]								
60	96	FIFO_WM_TH1	READ/WRITE	-							FIFO_WM_TH[9:8]	
61	97	FIFO_WM_TH2	READ/WRITE	FIFO_WM_TH[7:0]								
68	104	SIGNAL_PATH_RESET	READ/WRITE	-							ACCEL_RST	TEMP_RST
69	105	ACCEL_INTEL_CTRL	READ/WRITE	ACCEL_INT_EL_EN	ACCEL_INTEL_MODE	-				OUTPUT_LIMIT	WOM_TH_MODE	
6A	106	USER_CTRL	READ/WRITE	-	FIFO_EN	-			FIFO_RST	-	SIG_COND_RST	
6B	107	PWR_MGMT_1	READ/WRITE	DEVICE_RESET	SLEEP	CYCLE	GYRO_STANDBY	TEMP_DIS	CLKSEL[2:0]			
6C	108	PWR_MGMT_2	READ/WRITE	-		STBY_XA	STBY_YA	STBY_ZA	STBY_XG	STBY_YG	STBY_ZG	

ADDR (HEX)	ADDR (DEC.)	REGISTER NAME	SERIAL I/F	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0
70	112	I2C_IF	READ/ WRITE	-	I2C_IF_DIS						
72	114	FIFO_COUNTH	READ	FIFO_COUNT[15:8]							
73	115	FIFO_COUNTL	READ	FIFO_COUNT[7:0]							
74	116	FIFO_R_W	READ/ WRITE	FIFO_DATA[7:0]							
75	117	WHO_AM_I	READ	WHOAMI[7:0]							
77	119	XA_OFFSET_H	READ/ WRITE	XA_OFFS [14:7]							
78	120	XA_OFFSET_L	READ/ WRITE	XA_OFFS [6:0]							
7A	122	YA_OFFSET_H	READ/ WRITE	YA_OFFS [14:7]							
7B	123	YA_OFFSET_L	READ/ WRITE	YA_OFFS [6:0]							
7D	125	ZA_OFFSET_H	READ/ WRITE	ZA_OFFS [14:7]							
7E	126	ZA_OFFSET_L	READ/ WRITE	ZA_OFFS [6:0]							

**Table 15. MPU-6886 Register Map**

**NOTE:** Register Names ending in \_H and \_L contain the high and low bytes, respectively, of an internal register value.

The reset value is 0x00 for all registers other than the registers below, also the self-test registers contain pre-programmed values and will not be 0x00 after reset.

- Register 26 (0x80) CONFIG
- Register 107 (0x41) Power Management 1
- Register 117 (0x19) WHO\_AM\_I

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## 8 REGISTER DESCRIPTIONS

This section describes the function and contents of each register within the MPU-6886.

**NOTE:** The device will come up in sleep mode upon power-up.

### 8.1 REGISTER 04 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER

**Register Name:** XG\_OFFS\_TC\_H

**Register Type:** READ/WRITE

**Register Address:** 04 (Decimal); 04 (Hex)

BIT	NAME	FUNCTION
[7:2]	XG_OFFS_LP[5:0]	Stores the offset shift in the gyroscope output from low noise mode to low power mode to be implemented as a correction in the customer software. 2's complement digital code, 0.125 dps/LSB from 3.875 dps to -4 dps.
[1:0]	XG_OFFS_TC_H[9:8]	Bits 9 and 8 of the 10-bit offset of X gyroscope (2's complement).

### 8.2 REGISTER 05 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER

**Register Name:** XG\_OFFS\_TC\_L

**Register Type:** READ/WRITE

**Register Address:** 05 (Decimal); 05 (Hex)

BIT	NAME	FUNCTION
[7:0]	XG_OFFS_TC_L[7:0]	Bits 7 to 0 of the 10-bit offset of X gyroscope (2's complement).

#### **Description:**

The temperature compensation (TC) registers are used to reduce gyro offset variation due to temperature change. The TC feature is always enabled. However the compensation only happens when a TC coefficient is programmed during factory trim which gets loaded into these registers at power up or after a *DEVICE\_RESET*. If these registers contain a value of zero, temperature compensation has no effect on the offset of the chip. The TC registers have a 10-bit magnitude and sign adjustment in all full scale modes with a resolution of 2.52 mdps/C steps.

If these registers contain a non-zero value after power up, the user may write zeros to them to see the offset values without TC with temperature variation. Note that doing so may result in offset values that exceed data sheet "Initial ZRO Tolerance" in other than normal ambient temperature (~25 °C). The TC coefficients maybe restored by the user with a power up or a *DEVICE\_RESET*.

The above description also applies to registers 7-8 and 10-11 in sections 8.3, 8.4, 8.5, and 8.6.



**8.3 REGISTER 07 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER**

Register Name: YG\_OFFS\_TC\_H

Register Type: READ/WRITE

Register Address: 07 (Decimal); 07 (Hex)

BIT	NAME	FUNCTION
[7:2]	YG_OFFS_LP[5:0]	Stores the offset shift in the gyroscope output from low noise mode to low power mode to be implemented as a correction in the customer software. 2's complement digital code, 0.125 dps/LSB from 3.875 dps to -4 dps.
[1:0]	YG_OFFS_TC_H[9:8]	Bits 9 and 8 of the 10-bit offset of Y gyroscope (2's complement).

**8.4 REGISTER 08 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER**

Register Name: YG\_OFFS\_TC\_L

Register Type: READ/WRITE

Register Address: 08 (Decimal); 08 (Hex)

BIT	NAME	FUNCTION
[7:0]	YG_OFFS_TC_L[7:0]	Bits 7 to 0 of the 10-bit offset of Y gyroscope (2's complement).

**8.5 REGISTER 10 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER**

Register Name: ZG\_OFFS\_TC\_H

Register Type: READ/WRITE

Register Address: 10 (Decimal); 0A (Hex)

BIT	NAME	FUNCTION
[7:2]	ZG_OFFS_LP[5:0]	Stores the offset shift in the gyroscope output from low noise mode to low power mode to be implemented as a correction in the customer software. 2's complement digital code, 0.125 dps/LSB from 3.875 dps to -4 dps.
[1:0]	ZG_OFFS_TC_H[9:8]	Bits 9 and 8 of the 10-bit offset of Z gyroscope (2's complement).

**8.6 REGISTER 11 – GYROSCOPE LOW NOISE TO LOW POWER OFFSET SHIFT AND GYROSCOPE OFFSET TEMPERATURE COMPENSATION (TC) REGISTER**

Register Name: ZG\_OFFS\_TC\_L

Register Type: READ/WRITE

Register Address: 11 (Decimal); 0B (Hex)

BIT	NAME	FUNCTION
[7:0]	ZG_OFFS_TC_L[7:0]	Bits 7 to 0 of the 10-bit offset of Z gyroscope (2's complement).

### 8.7 REGISTERS 13 TO 15 – ACCELEROMETER SELF-TEST REGISTERS

**Register Name:** SELF\_TEST\_X\_ACCEL, SELF\_TEST\_Y\_ACCEL, SELF\_TEST\_Z\_ACCEL

**Type:** READ/WRITE

**Register Address:** 13, 14, 15 (Decimal); 0D, 0E, 0F (Hex)

REGISTER	BITS	NAME	FUNCTION
SELF_TEST_X_ACCEL	[7:0]	XA_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.
SELF_TEST_Y_ACCEL	[7:0]	YA_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.
SELF_TEST_Z_ACCEL	[7:0]	ZA_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.

The equation to convert self-test codes in OTP to factory self-test measurement is:

$$ST\_OTP = (2620 / 2^{FS}) * 1.01^{(ST\_code-1)} \text{ (lsb)}$$

where ST\_OTP is the value that is stored in OTP of the device, FS is the Full Scale value, and ST\_code is based on the Self-Test value (ST\_FAC) determined in InvenSense’s factory final test and calculated based on the following equation:

$$ST\_code = round\left(\frac{\log(ST\_FAC / (2620 / 2^{FS}))}{\log(1.01)}\right) + 1$$

### 8.8 REGISTER 19 – X-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE

**Register Name:** XG\_OFFS\_USRH

**Register Type:** READ/WRITE

**Register Address:** 19 (Decimal); 13 (Hex)

BIT	NAME	FUNCTION
[7:0]	X_OFFS_USR[15:8]	Bits 15 to 8 of the 16-bit offset of X gyroscope (2’s complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.9 REGISTER 20 – X-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE

**Register Name:** XG\_OFFS\_USRL

**Register Type:** READ/WRITE

**Register Address:** 20 (Decimal); 14 (Hex)

BIT	NAME	FUNCTION
[7:0]	X_OFFS_USR[7:0]	Bits 7 to 0 of the 16-bit offset of X gyroscope (2’s complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.10 REGISTER 21 – Y-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE

Register Name: YG\_OFFS\_USRH

Register Type: READ/WRITE

Register Address: 21 (Decimal); 15 (Hex)

BIT	NAME	FUNCTION
[7:0]	Y_OFFS_USR[15:8]	Bits 15 to 8 of the 16-bit offset of Y gyroscope (2's complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.11 REGISTER 22 – Y-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE

Register Name: YG\_OFFS\_USRL

Register Type: READ/WRITE

Register Address: 22 (Decimal); 16 (Hex)

BIT	NAME	FUNCTION
[7:0]	Y_OFFS_USR[7:0]	Bits 7 to 0 of the 16-bit offset of Y gyroscope (2's complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.12 REGISTER 23 – Z-GYRO OFFSET ADJUSTMENT REGISTER – HIGH BYTE

Register Name: ZG\_OFFS\_USRH

Register Type: READ/WRITE

Register Address: 23 (Decimal); 17 (Hex)

BIT	NAME	FUNCTION
[7:0]	Z_OFFS_USR[15:8]	Bits 15 to 8 of the 16-bit offset of Z gyroscope (2's complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.13 REGISTER 24 – Z-GYRO OFFSET ADJUSTMENT REGISTER – LOW BYTE

Register Name: ZG\_OFFS\_USRL

Register Type: READ/WRITE

Register Address: 24 (Decimal); 18 (Hex)

BIT	NAME	FUNCTION
[7:0]	Z_OFFS_USR[7:0]	Bits 7 to 0 of the 16-bit offset of Z gyroscope (2's complement). This register is used to remove DC bias from the sensor output. The value in this register is added to the gyroscope sensor value before going into the sensor register.

### 8.14 REGISTER 25 – SAMPLE RATE DIVIDER

Register Name: SMPLRT\_DIV

Register Type: READ/WRITE

Register Address: 25 (Decimal); 19 (Hex)

BIT	NAME	FUNCTION
[7:0]	SMPLRT_DIV[7:0]	Divides the internal sample rate (see register CONFIG) to generate the sample rate that controls sensor data output rate, FIFO sample rate. <b>NOTE:</b> This register is only effective when FCHOICE_B register bits are 2'b00, and (0 < DLPF_CFG < 7). This is the update rate of the sensor register: $SAMPLE\_RATE = INTERNAL\_SAMPLE\_RATE / (1 + SMPLRT\_DIV)$ Where INTERNAL_SAMPLE_RATE = 1 kHz

**8.15 REGISTER 26 – CONFIGURATION**

**Register Name: CONFIG**

**Register Type: READ/WRITE**

**Register Address: 26 (Decimal); 1A (Hex)**

BIT	NAME	FUNCTION																		
[7]	-	Default configuration value is 1. User should set it to 0.																		
[6]	FIFO_MODE	When set to '1', when the FIFO is full, additional writes will not be written to FIFO. When set to '0', when the FIFO is full, additional writes will be written to the FIFO, replacing the oldest data.																		
[5:3]	EXT_SYNC_SET[2:0]	Enables the FSYNC pin data to be sampled. <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>EXT_SYNC_SET</th> <th>FSYNC BIT LOCATION</th> </tr> </thead> <tbody> <tr><td>0</td><td>function disabled</td></tr> <tr><td>1</td><td>TEMP_OUT_L[0]</td></tr> <tr><td>2</td><td>GYRO_XOUT_L[0]</td></tr> <tr><td>3</td><td>GYRO_YOUT_L[0]</td></tr> <tr><td>4</td><td>GYRO_ZOUT_L[0]</td></tr> <tr><td>5</td><td>ACCEL_XOUT_L[0]</td></tr> <tr><td>6</td><td>ACCEL_YOUT_L[0]</td></tr> <tr><td>7</td><td>ACCEL_ZOUT_L[0]</td></tr> </tbody> </table> <p>FSYNC will be latched to capture short strobes. This will be done such that if FSYNC toggles, the latched value toggles, but won't toggle again until the new latched value is captured by the sample rate strobe.</p>	EXT_SYNC_SET	FSYNC BIT LOCATION	0	function disabled	1	TEMP_OUT_L[0]	2	GYRO_XOUT_L[0]	3	GYRO_YOUT_L[0]	4	GYRO_ZOUT_L[0]	5	ACCEL_XOUT_L[0]	6	ACCEL_YOUT_L[0]	7	ACCEL_ZOUT_L[0]
EXT_SYNC_SET	FSYNC BIT LOCATION																			
0	function disabled																			
1	TEMP_OUT_L[0]																			
2	GYRO_XOUT_L[0]																			
3	GYRO_YOUT_L[0]																			
4	GYRO_ZOUT_L[0]																			
5	ACCEL_XOUT_L[0]																			
6	ACCEL_YOUT_L[0]																			
7	ACCEL_ZOUT_L[0]																			
[2:0]	DLPF_CFG[2:0]	For the DLPF to be used, FCHOICE_B[1:0] is 2'b00. See Table 16.																		

The DLPF is configured by *DLPF\_CFG*, when *FCHOICE\_B* [1:0] = 2'b00. The gyroscope and temperature sensor are filtered according to the value of *DLPF\_CFG* and *FCHOICE\_B* as shown in the table below.

FCHOICE_B		DLPF_CFG	GYROSCOPE			TEMPERATURE SENSOR
<1>	<0>		3-DB BW (HZ)	NOISE BW (HZ)	RATE (KHZ)	3-DB BW (HZ)
X	1	X	8173	8595.1	32	4000
1	0	X	3281	3451.0	32	4000
0	0	0	250	306.6	8	4000
0	0	1	176	177.0	1	188
0	0	2	92	108.6	1	98
0	0	3	41	59.0	1	42
0	0	4	20	30.5	1	20
0	0	5	10	15.6	1	10
0	0	6	5	8.0	1	5
0	0	7	3281	3451.0	8	4000

**Table 16. Configuration**

### 8.16 REGISTER 27 – GYROSCOPE CONFIGURATION

Register Name: GYRO\_CONFIG

Register Type: READ/WRITE

Register Address: 27 (Decimal); 1B (Hex)

BIT	NAME	FUNCTION
[7]	XG_ST	X Gyro self-test.
[6]	YG_ST	Y Gyro self-test.
[5]	ZG_ST	Z Gyro self-test.
[4:3]	FS_SEL[1:0]	Gyro Full Scale Select: 00 = $\pm 250$ dps. 01 = $\pm 500$ dps. 10 = $\pm 1000$ dps. 11 = $\pm 2000$ dps.
[2]	-	Reserved.
[1:0]	FCHOICE_B[1:0]	Used to bypass DLPF as shown in Table 16.

### 8.17 REGISTER 28 – ACCELEROMETER CONFIGURATION

Register Name: ACCEL\_CONFIG

Register Type: READ/WRITE

Register Address: 28 (Decimal); 1C (Hex)

BIT	NAME	FUNCTION
[7]	XA_ST	X Accel self-test.
[6]	YA_ST	Y Accel self-test.
[5]	ZA_ST	Z Accel self-test.
[4:3]	ACCEL_FS_SEL[1:0]	Accel Full Scale Select: $\pm 2g$ (00), $\pm 4g$ (01), $\pm 8g$ (10), $\pm 16g$ (11)
[2:0]	-	Reserved.

### 8.18 REGISTER 29 – ACCELEROMETER CONFIGURATION 2

Register Name: ACCEL\_CONFIG2

Register Type: READ/WRITE

Register Address: 29 (Decimal); 1D (Hex)

BIT	NAME	FUNCTION
[5:4]	DEC2_CFG[1:0]	Averaging filter settings for Low Power Accelerometer mode: 0 = Average 4 samples. 1 = Average 8 samples. 2 = Average 16 samples. 3 = Average 32 samples.
[3]	ACCEL_FCHOICE_B	Used to bypass DLPF as shown in the table below.
[2:0]	A_DLPF_CFG	Accelerometer low pass filter setting as shown in Table 18.

ACCEL_FCHOICE_B	A_DLPF_CFG	ACCELEROMETER		
		3-DB BW (HZ)	NOISE BW (HZ)	RATE (KHZ)
1	X	1046.0	1100.0	4
0	0	218.1	235.0	1
0	1	218.1	235.0	1
0	2	99.0	121.3	1

ACCEL_FCHOICE_B	A_DLPF_CFG	ACCELEROMETER		
		3-DB BW (HZ)	NOISE BW (HZ)	RATE (KHZ)
0	3	44.8	61.5	1
0	4	21.2	31.0	1
0	5	10.2	15.5	1
0	6	5.1	7.8	1
0	7	420.0	441.6	1

**Table 17. Accelerometer Data Rates and Bandwidths (Low-Noise Mode)**

The data output rate of the DLPF filter block can be further reduced by a factor of  $1/(1+SMPLRT\_DIV)$ , where SMPLRT\_DIV is an 8-bit integer. Following is a small subset of ODRs that are configurable for the accelerometer in the low-noise mode in this manner (Hz):

3.91, 7.81, 15.63, 31.25, 62.50, 125, 250, 500, 1K

The following table lists the approximate accelerometer filter bandwidths available in the low-power mode of operation for some example ODRs.

In the low-power mode of operation, the accelerometer is duty-cycled. Table 18 shows some example configurations for accelerometer low power mode.

	AVERAGES	1x	4x	8x	16x	32x
	ACCEL_FCHOICE_B		1	0	0	0
DEC2_CFG		X	0	1	2	3
A_DLPF_CFG		X	7	7	7	7
TON (MS)		1.084	1.84	2.84	4.84	8.84
NBW (HZ)		1100	442	236	122	62
3-DB BW (HZ)		1046	420	219	111	56
NOISE (MG-RMS)		4.8	3.0	2.2	1.6	1.1
SMPLRT_DIV	ODR (HZ)	LOW-POWER ACCELEROMETER MODE CURRENT CONSUMPTION (µA)				
255	3.91	9.4	10.2	11.5	13.8	18.5
127	7.81	10.7	12.4	14.7	19.6	28.9
99	10	11.4	13.7	16.6	22.6	34.7
63	15.63	13.3	16.7	21.5	30.8	49.7
31	31.25	18.3	25.4	34.8	53.6	91.2
19	50	24.4	35.8	50.8	80.8	141.1
15	62.5	28.4	42.7	61.5	99.0	174.3
9	100	40.7	63.5	93.6	153.7	303.3
7	125	48.8	77.4	114.8	190.1	N/A
4	200	73.4	118.8	178.9	299.3	
3	250	89.6	146.5	221.6	N/A	
1	500	171.1	284.9	N/A		

**Table 18. Approximate Accelerometer Filter Bandwidths (Low-Power Mode)**

**8.19 REGISTER 30 – GYROSCOPE LOW POWER MODE CONFIGURATION**

**Register Name:** LP\_MODE\_CFG

**Register Type:** READ/WRITE

**Register Address:** 30 (Decimal); 1E (Hex)

BIT	NAME	FUNCTION
[7]	GYRO_CYCLE	When set to '1' low-power gyroscope mode is enabled. Default setting is '0'.
[6:4]	G_AVGCFG[2:0]	Averaging filter configuration for low-power gyroscope mode. Default setting is '000'.
[3:0]	-	Reserved.

To operate in gyroscope low-power mode or 6-axis low-power mode, GYRO\_CYCLE should be set to '1.' Gyroscope filter configuration is determined by G\_AVGCFG[2:0] that sets the averaging filter configuration. It is not dependent on DLPF\_CFG[2:0].

	AVERAGES	1X	2X	4X	8X	16X	32X	64X	128X
	G_AVGCFG	0	1	2	3	4	5	6	7
	NBW (HZ)	650.8	407.1	224.2	117.4	60.2	30.6	15.6	8.0
	3-DB BW (HZ)	622	391	211	108	54	27	14	7
SMP_LRT_DIV	ODR (HZ)	LOW-POWER GYROSCOPE MODE CURRENT CONSUMPTION (MA)							
255	3.9	0.79	0.80	0.80	0.82	0.85	0.90	1.01	1.23
99	10.0	0.81	0.82	0.84	0.87	0.95	1.09	1.37	1.94
65	15.2	0.83	0.84	0.87	0.92	1.03	1.24	1.67	2.53
64	15.4	0.83	0.84	0.87	0.92	1.03	1.25	1.69	N/A
33	29.4	0.87	0.90	0.95	1.05	1.26	1.68	2.51	N/A
32	30.3	0.87	0.90	0.95	1.06	1.28	1.70	N/A	N/A
19	50.0	0.93	0.98	1.06	1.24	1.60	2.30	N/A	N/A
17	55.6	0.95	1.00	1.10	1.29	1.69	2.47	N/A	N/A
16	58.8	0.96	1.01	1.11	1.32	1.74	N/A	N/A	N/A
9	100.0	1.08	1.17	1.35	1.70	2.41	N/A	N/A	N/A
7	125.0	1.16	1.27	1.49	1.93	N/A	N/A	N/A	N/A
6	142.9	1.21	1.34	1.59	2.09	N/A	N/A	N/A	N/A
4	200.0	1.38	1.56	1.91	N/A	N/A	N/A	N/A	N/A
3	250.0	1.53	1.75	2.19	N/A	N/A	N/A	N/A	N/A
2	333.3	1.78	2.07	N/A	N/A	N/A	N/A	N/A	N/A

Table 19. Example Gyroscope Configurations (Low-Power Mode)

**8.20 REGISTER 32 – WAKE-ON MOTION THRESHOLD (X-AXIS ACCELEROMETER)**

**Register Name:** ACCEL\_WOM\_X\_THR

**Register Type:** READ/WRITE

**Register Address:** 32 (Decimal); 20 (Hex)

BIT	NAME	FUNCTION
[7:0]	WOM_X_TH[7:0]	This register holds the threshold value for the Wake on Motion Interrupt for X-axis accelerometer.

### 8.21 REGISTER 33 – WAKE-ON MOTION THRESHOLD (Y-AXIS ACCELEROMETER)

**Register Name:** ACCEL\_WOM\_Y\_THR

**Register Type:** READ/WRITE

**Register Address:** 33 (Decimal); 21 (Hex)

BIT	NAME	FUNCTION
[7:0]	WOM_Y_TH[7:0]	This register holds the threshold value for the Wake on Motion Interrupt for Y-axis accelerometer.

### 8.22 REGISTER 34 – WAKE-ON MOTION THRESHOLD (Z-AXIS ACCELEROMETER)

**Register Name:** ACCEL\_WOM\_Z\_THR

**Register Type:** READ/WRITE

**Register Address:** 34 (Decimal); 22 (Hex)

BIT	NAME	FUNCTION
[7:0]	WOM_Z_TH[7:0]	This register holds the threshold value for the Wake on Motion Interrupt for Z-axis accelerometer.

### 8.23 REGISTER 35 – FIFO ENABLE

**Register Name:** FIFO\_EN

**Register Type:** READ/WRITE

**Register Address:** 35 (Decimal); 23 (Hex)

BIT	NAME	FUNCTION
[7:5]	-	Reserved.
[4]	GYRO_FIFO_EN	1 – Write TEMP_OUT_H, TEMP_OUT_L, GYRO_XOUT_H, GYRO_XOUT_L, GYRO_YOUT_H, GYRO_YOUT_L, GYRO_ZOUT_H, and GYRO_ZOUT_L to the FIFO at the sample rate; If enabled, buffering of data occurs even if data path is in standby. 0 – Function is disabled.
[3]	ACCEL_FIFO_EN	1 – Write ACCEL_XOUT_H, ACCEL_XOUT_L, ACCEL_YOUT_H, ACCEL_YOUT_L, ACCEL_ZOUT_H, ACCEL_ZOUT_L, TEMP_OUT_H, and TEMP_OUT_L to the FIFO at the sample rate; 0 – Function is disabled.
[2:0]	-	Reserved.

**NOTE:** If both GYRO\_FIFO\_EN And ACCEL\_FIFO\_EN are 1, write ACCEL\_XOUT\_H, ACCEL\_XOUT\_L, ACCEL\_YOUT\_H, ACCEL\_YOUT\_L, ACCEL\_ZOUT\_H, ACCEL\_ZOUT\_L, TEMP\_OUT\_H, TEMP\_OUT\_L, GYRO\_XOUT\_H, GYRO\_XOUT\_L, GYRO\_YOUT\_H, GYRO\_YOUT\_L, GYRO\_ZOUT\_H, and GYRO\_ZOUT\_L to the FIFO at the sample rate.

### 8.24 REGISTER 54 – FSYNC INTERRUPT STATUS

**Register Name:** FSYNC\_INT

**Register Type:** READ to CLEAR

**Register Address:** 54 (Decimal); 36 (Hex)

BIT	NAME	FUNCTION
[7]	FSYNC_INT	This bit automatically sets to 1 when a FSYNC interrupt has been generated. The bit clears to 0 after the register has been read.



### 8.25 REGISTER 55 – INT/DRDY PIN / BYPASS ENABLE CONFIGURATION

**Register Name:** INT\_PIN\_CFG

**Register Type:** READ/WRITE

**Register Address:** 55 (Decimal); 37 (Hex)

BIT	NAME	FUNCTION
[7]	INT_LEVEL	1 – The logic level for INT/DRDY pin is active low. 0 – The logic level for INT/DRDY pin is active high.
[6]	INT_OPEN	1 – INT/DRDY pin is configured as open drain. 0 – INT/DRDY pin is configured as push-pull.
[5]	LATCH_INT_EN	1 – INT/DRDY pin level held until interrupt status is cleared. 0 – INT/DRDY pin indicates interrupt pulse’s width is 50 $\mu$ s.
[4]	INT_RD_CLEAR	1 – Interrupt status is cleared if any read operation is performed. 0 – Interrupt status is cleared only by reading INT_STATUS register.
[3]	FSYNC_INT_LEVEL	1 – The logic level for the FSYNC pin as an interrupt is active low. 0 – The logic level for the FSYNC pin as an interrupt is active high.
[2]	FSYNC_INT_MODE_EN	When this bit is equal to 1, the FSYNC pin will trigger an interrupt when it transitions to the level specified by FSYNC_INT_LEVEL. When this bit is equal to 0, the FSYNC pin is disabled from causing an interrupt.
[1:0]	-	Reserved.

### 8.26 REGISTER 56 – INTERRUPT ENABLE

**Register Name:** INT\_ENABLE

**Register Type:** READ/WRITE

**Register Address:** 56 (Decimal); 38 (Hex)

BIT	NAME	FUNCTION
[7]	WOM_X_INT_EN	1 – Enable WoM interrupt on X-axis accelerometer. Default setting is 0.
[6]	WOM_Y_INT_EN	1 – Enable WoM interrupt on Y-axis accelerometer. Default setting is 0.
[5]	WOM_Z_INT_EN	1 – Enable WoM interrupt on Z-axis accelerometer. Default setting is 0.
[4]	FIFO_OFLOW_EN	1 – Enables a FIFO buffer overflow to generate an interrupt. 0 – Function is disabled.
[3]	-	Reserved.
[2]	GDRIVE_INT_EN	Gyroscope Drive System Ready interrupt enable.
[1]	-	Reserved.
[0]	DATA_RDY_INT_EN	Data ready interrupt enable.

### 8.27 REGISTER 57 – FIFO WATERMARK INTERRUPT STATUS

**Register Name:** FIFO\_WM\_INT\_STATUS

**Register Type:** READ to CLEAR

**Register Address:** 57 (Decimal); 39 (Hex)

BIT	NAME	FUNCTION
[6]	FIFO_WM_INT	FIFO Watermark interrupt status. Cleared on Read.

## 8.28 REGISTER 58 – INTERRUPT STATUS

**Register Name:** INT\_STATUS

**Register Type:** READ to CLEAR

**Register Address:** 58 (Decimal); 3A (Hex)

BIT	NAME	FUNCTION
[7]	WOM_X_INT	X-axis accelerometer WoM interrupt status. Cleared on Read.
[6]	WOM_Y_INT	Y-axis accelerometer WoM interrupt status. Cleared on Read.
[5]	WOM_Z_INT	Z-axis accelerometer WoM interrupt status. Cleared on Read.
[4]	FIFO_OFLOW_INT	This bit automatically sets to 1 when a FIFO buffer overflow has been generated. The bit clears to 0 after the register has been read.
[3]	-	Reserved.
[2]	GDRIVE_INT	Gyroscope Drive System Ready interrupt.
[1]	-	Reserved.
[0]	DATA_RDY_INT	This bit automatically sets to 1 when a Data Ready interrupt is generated. The bit clears to 0 after the register has been read.

## 8.29 REGISTERS 59 TO 64 – ACCELEROMETER MEASUREMENTS

**Register Name:** ACCEL\_XOUT\_H

**Register Type:** READ only

**Register Address:** 59 (Decimal); 3B (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_XOUT[15:8]	High byte of accelerometer x-axis data.

**Register Name:** ACCEL\_XOUT\_L

**Register Type:** READ only

**Register Address:** 60 (Decimal); 3C (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_XOUT[7:0]	Low byte of accelerometer x-axis data.

**Register Name:** ACCEL\_YOUT\_H

**Register Type:** READ only

**Register Address:** 61 (Decimal); 3D (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_YOUT[15:8]	High byte of accelerometer y-axis data.

**Register Name:** ACCEL\_YOUT\_L

**Register Type:** READ only

**Register Address:** 62 (Decimal); 3E (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_YOUT[7:0]	Low byte of accelerometer y-axis data.

**Register Name:** ACCEL\_ZOUT\_H

**Register Type:** READ only

**Register Address:** 63 (Decimal); 3F (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_ZOUT[15:8]	High byte of accelerometer z-axis data.

Register Name: ACCEL\_ZOUT\_L

Register Type: READ only

Register Address: 64 (Decimal); 40 (Hex)

BIT	NAME	FUNCTION
[7:0]	ACCEL_ZOUT[7:0]	Low byte of accelerometer z-axis data.

### 8.30 REGISTERS 65 AND 66 – TEMPERATURE MEASUREMENT

Register Name: TEMP\_OUT\_H

Register Type: READ only

Register Address: 65 (Decimal); 41 (Hex)

BIT	NAME	FUNCTION
[7:0]	TEMP_OUT[15:8]	Low byte of the temperature sensor output

Register Name: TEMP\_OUT\_L

Register Type: READ only

Register Address: 66 (Decimal); 42 (Hex)

BIT	NAME	FUNCTION
[7:0]	TEMP_OUT[7:0]	High byte of the temperature sensor output $TEMP\_degC = (TEMP\_OUT[15:0]/Temp\_Sensitivity) + RoomTemp\_Offset$ where Temp_Sensitivity = 326.8 LSB/°C and RoomTemp_Offset = 25°C

### 8.31 REGISTERS 67 TO 72 – GYROSCOPE MEASUREMENTS

Register Name: GYRO\_XOUT\_H

Register Type: READ only

Register Address: 67 (Decimal); 43 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_XOUT[15:8]	High byte of the X-Axis gyroscope output.

Register Name: GYRO\_XOUT\_L

Register Type: READ only

Register Address: 68 (Decimal); 44 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_XOUT[7:0]	Low byte of the X-Axis gyroscope output $GYRO\_XOUT = Gyro\_Sensitivity * X\_angular\_rate$ Nominal FS_SEL = 0 Conditions Gyro_Sensitivity = 131 LSB/(dps)

Register Name: GYRO\_YOUT\_H

Register Type: READ only

Register Address: 69 (Decimal); 45 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_YOUT[15:8]	High byte of the Y-Axis gyroscope output.

**Register Name:** GYRO\_YOUT\_L

**Register Type:** READ only

**Register Address:** 70 (Decimal); 46 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_YOUT[7:0]	Low byte of the Y-Axis gyroscope output <b>GYRO_YOUT</b> = Gyro_Sensitivity * Y_angular_rate Nominal FS_SEL = 0 Conditions Gyro_Sensitivity = 131 LSB/(dps)

**Register Name:** GYRO\_ZOUT\_H

**Register Type:** READ only

**Register Address:** 71 (Decimal); 47 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_ZOUT[15:8]	High byte of the Z-Axis gyroscope output.

**Register Name:** GYRO\_ZOUT\_L

**Register Type:** READ only

**Register Address:** 72 (Decimal); 48 (Hex)

BIT	NAME	FUNCTION
[7:0]	GYRO_ZOUT[7:0]	Low byte of the Z-Axis gyroscope output <b>GYRO_ZOUT</b> = Gyro_Sensitivity * Z_angular_rate Nominal FS_SEL = 0 Conditions Gyro_Sensitivity = 131 LSB/(dps)

### 8.32 REGISTERS 80 TO 82 – GYROSCOPE SELF-TEST REGISTERS

**Register Name:** SELF\_TEST\_X\_GYRO, SELF\_TEST\_Y\_GYRO, SELF\_TEST\_Z\_GYRO

**Type:** READ/WRITE

**Register Address:** 80, 81, 82 (Decimal); 50, 51, 52 (Hex)

REGISTER	BIT	NAME	FUNCTION
SELF_TEST_X_GYRO	[7:0]	XG_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.
SELF_TEST_Y_GYRO	[7:0]	YG_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.
SELF_TEST_Z_GYRO	[7:0]	ZG_ST_DATA[7:0]	The value in this register indicates the self-test output generated during manufacturing tests. This value is to be used to check against subsequent self-test outputs performed by the end user.

The equation to convert self-test codes in OTP to factory self-test measurement is:

$$ST\_OTP = (2620 / 2^{FS}) * 1.01^{(ST\_code-1)} \text{ (lsb)}$$

where ST\_OTP is the value that is stored in OTP of the device, FS is the Full Scale value, and ST\_code is based on the Self-Test value (ST\_FAC) determined in InvenSense’s factory final test and calculated based on the following equation:

$$ST\_code = round\left(\frac{\log(ST\_FAC / (2620 / 2^{FS}))}{\log(1.01)}\right) + 1$$

### 8.33 REGISTERS 83 TO 90 – ENGINEERING ID REGISTERS

**Register Name:** E\_ID0 – E\_ID6

Type: READ/WRITE

Register Address: 83 - 89 (Decimal); 53 – 59 (Hex)

REGISTER	BIT	NAME	FUNCTION
E_ID0	[7:0]	ENGINEERING_ID0[7:0]	Engineering ID.
E_ID1	[7:0]	ENGINEERING_ID1[7:0]	Engineering ID.
E_ID2	[7:0]	ENGINEERING_ID2[7:0]	Engineering ID.
E_ID3	[7:0]	ENGINEERING_ID3[7:0]	Engineering ID.
E_ID4	[7:0]	ENGINEERING_ID4[7:0]	Engineering ID.
E_ID5	[7:0]	ENGINEERING_ID5[7:0]	Engineering ID.
E_ID6	[7:0]	ENGINEERING_ID6[7:0]	Engineering ID.

### 8.34 REGISTER 96-97 – FIFO WATERMARK THRESHOLD IN NUMBER OF BYTES

Register Name: FIFO\_WM\_TH1

Register Type: READ/WRITE

Register Address: 96 (Decimal); 60 (Hex)

BIT	NAME	FUNCTION
[1:0]	FIFO_WM_TH[9:8]	FIFO watermark threshold in number of bytes. Watermark interrupt is disabled if the threshold is set to "0". Default value is 00000000.

Register Name: FIFO\_WM\_TH2

Register Type: READ/WRITE

Register Address: 97 (Decimal); 61 (Hex)

BIT	NAME	FUNCTION
[7:0]	FIFO_WM_TH[7:0]	FIFO watermark threshold in number of bytes. Watermark interrupt is disabled if the threshold is set to "0". Default value is 00000000.

The register FIFO\_WM\_TH[9:0] sets the FIFO watermark threshold level (0 - 1023). User should ensure that bit 7 of register 0x1A is set to 0 before using this feature. When the FIFO count is at or above the watermark level ( $FIFO\_COUNT[15:0] \geq FIFO\_WM\_TH[9:0]$ ) and the system is not in the middle of a FIFO read, an interrupt is triggered. The interrupt will set the FIFO watermark interrupt status register field FIFO\_WM\_INT = 1, and the INT pin will issue a pulse if configured in pulse mode, or set to the active level if configured in latch mode. Register bit FIFO\_WM\_INT is not read-to-clear, unlike the other interrupts. Rather, whenever FIFO\_R\_W register is read, FIFO\_WM\_INT status bit is cleared automatically. At the same time, the INT pin will be cleared as well if it is configured in latch mode.

The FIFO watermark interrupt and the INT pin are cleared upon the first read (and only the first read) of the FIFO. If, at the end of the FIFO read, the FIFO count is at or above the watermark level, the interrupt status bit and INT pin will again be set. If the INT pin is configured for latched operation, it will wait until the host completes the read to set to the active level.

When FIFO\_WM\_TH = 0, the FIFO watermark interrupt is disabled.

### 8.35 REGISTER 104 – SIGNAL PATH RESET

**Register Name:** SIGNAL\_PATH\_RESET

**Register Type:** READ/WRITE

**Register Address:** 104 (Decimal); 68 (Hex)

BIT	NAME	FUNCTION
[7:2]	-	Reserved.
[1]	ACCEL_RST	Reset accel digital signal path. <b>NOTE:</b> Sensor registers are not cleared. Use SIG_COND_RST to clear sensor registers.
[0]	TEMP_RST	Reset temp digital signal path. <b>NOTE:</b> Sensor registers are not cleared. Use SIG_COND_RST to clear sensor registers.

### 8.36 REGISTER 105 – ACCELEROMETER INTELLIGENCE CONTROL

**Register Name:** ACCEL\_INTEL\_CTRL

**Register Type:** READ/WRITE

**Register Address:** 105 (Decimal); 69 (Hex)

BIT	NAME	FUNCTION
[7]	ACCEL_INTEL_EN	This bit enables the Wake-on-Motion detection logic.
[6]	ACCEL_INTEL_MODE	0 – Do not use. 1 – Compare the current sample with the previous sample.
[5:2]	-	Reserved.
[1]	OUTPUT_LIMIT	To avoid limiting sensor output to less than 0x7E7F, set this bit to 1. This should be done every time the MPU-6886 is powered up.
[0]	WOM_TH_MODE	0 – Set WoM interrupt on the OR of all enabled accelerometer thresholds. 1 – Set WoM interrupt on the AND of all enabled accelerometer threshold. Default setting is 0.

### 8.37 REGISTER 106 – USER CONTROL

**Register Name:** USER\_CTRL

**Register Type:** READ/WRITE

**Register Address:** 106 (Decimal); 6A (Hex)

BIT	NAME	FUNCTION
[7]	-	Reserved.
[6]	FIFO_EN	1 – Enable FIFO operation mode. 0 – Disable FIFO access from serial interface.
[5]	-	Reserved.
[4]	-	Reserved.
[3]	-	Reserved.
[2]	FIFO_RST	1 – Reset FIFO module. Reset is asynchronous. This bit auto clears after one clock cycle of the internal 20 MHz clock.
[1]	-	Reserved.
[0]	SIG_COND_RST	1 – Reset all gyro digital signal path, accel digital signal path, and temp digital signal path. This bit also clears all the sensor registers.

**8.38 REGISTER 107 – POWER MANAGEMENT 1**

**Register Name: PWR\_MGMT\_1**

**Register Type: READ/WRITE**

**Register Address: 107 (Decimal); 6B (Hex)**

BIT	NAME	FUNCTION																		
[7]	DEVICE_RESET	1 – Reset the internal registers and restores the default settings. The bit automatically clears to 0 once the reset is done.																		
[6]	SLEEP	When set to 1, the chip is set to sleep mode.																		
[5]	CYCLE	When set to 1, and SLEEP and STANDBY are not set to 1, the chip will cycle between sleep and taking a single accelerometer sample at a rate determined by SMPLRT_DIV <b>NOTE:</b> When all accelerometer axes are disabled via PWR_MGMT_2 register bits and cycle is enabled the chip will wake up at the rate determined by the respective registers above, but will not take any samples.																		
[4]	GYRO_STANDBY	When set, the gyro drive and pll circuitry are enabled, but the sense paths are disabled. This is a low power mode that allows quick enabling of the gyros.																		
[3]	TEMP_DIS	When set to 1, this bit disables the temperature sensor.																		
[2:0]	CLKSEL[2:0]	<table border="1"> <thead> <tr> <th>CODE</th> <th>CLOCK SOURCE</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>Internal 20 MHz oscillator</td> </tr> <tr> <td>1</td> <td>Auto selects the best available clock source – PLL if ready, else use the Internal oscillator</td> </tr> <tr> <td>2</td> <td>Auto selects the best available clock source – PLL if ready, else use the Internal oscillator</td> </tr> <tr> <td>3</td> <td>Auto selects the best available clock source – PLL if ready, else use the Internal oscillator</td> </tr> <tr> <td>4</td> <td>Auto selects the best available clock source – PLL if ready, else use the Internal oscillator</td> </tr> <tr> <td>5</td> <td>Auto selects the best available clock source – PLL if ready, else use the Internal oscillator</td> </tr> <tr> <td>6</td> <td>Internal 20MHz oscillator</td> </tr> <tr> <td>7</td> <td>Stops the clock and keeps timing generator in reset</td> </tr> </tbody> </table>	CODE	CLOCK SOURCE	0	Internal 20 MHz oscillator	1	Auto selects the best available clock source – PLL if ready, else use the Internal oscillator	2	Auto selects the best available clock source – PLL if ready, else use the Internal oscillator	3	Auto selects the best available clock source – PLL if ready, else use the Internal oscillator	4	Auto selects the best available clock source – PLL if ready, else use the Internal oscillator	5	Auto selects the best available clock source – PLL if ready, else use the Internal oscillator	6	Internal 20MHz oscillator	7	Stops the clock and keeps timing generator in reset
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6	Internal 20MHz oscillator																			
7	Stops the clock and keeps timing generator in reset																			

**NOTE:** The default value of CLKSEL[2:0] is 001. CLKSEL[2:0] must be set to 001 to achieve full gyroscope performance.

**8.39 REGISTER 108 – POWER MANAGEMENT 2**

**Register Name: PWR\_MGMT\_2**

**Register Type: READ/WRITE**

**Register Address: 108 (Decimal); 6C (Hex)**

BIT	NAME	FUNCTION
[7]	-	Reserved.
[6]	-	Reserved.
[5]	STBY_XA	1 – X-accelerometer is disabled. 0 – X-accelerometer is on.
[4]	STBY_YA	1 – Y-accelerometer is disabled. 0 – Y-accelerometer is on.
[3]	STBY_ZA	1 – Z-accelerometer is disabled. 0 – Z-accelerometer is on.
[2]	STBY_XG	1 – X-gyro is disabled. 0 – X-gyro is on.
[1]	STBY_YG	1 – Y-gyro is disabled. 0 – Y-gyro is on.
[0]	STBY_ZG	1 – Z-gyro is disabled. 0 – Z-gyro is on.

### 8.40 REGISTER 112 – I<sup>2</sup>C INTERFACE

**Register Name:** I2C\_IF

**Register Type:** READ/WRITE

**Register Address:** 112 (Decimal); 70 (Hex)

BIT	NAME	FUNCTION
[7]	-	Reserved.
[6]	I2C_IF_DIS	1 – Disable I <sup>2</sup> C Slave module and put the serial interface in SPI mode only.
[5:0]	-	Reserved.

### 8.41 REGISTER 114 AND 115 – FIFO COUNT REGISTERS

**Register Name:** FIFO\_COUNTH

**Register Type:** READ Only

**Register Address:** 114 (Decimal); 72 (Hex)

BIT	NAME	FUNCTION
[7:0]	FIFO_COUNT[15:8]	High Bits, count indicates the number of written bytes in the FIFO. Reading this byte latches the data for both FIFO_COUNTH, and FIFO_COUNTL.

**Register Name:** FIFO\_COUNTL

**Register Type:** READ Only

**Register Address:** 115 (Decimal); 73 (Hex)

BIT	NAME	FUNCTION
[7:0]	FIFO_COUNT[7:0]	Low Bits, count indicates the number of written bytes in the FIFO. <b>NOTE:</b> Must read FIFO_COUNTL to latch new data for both FIFO_COUNTH and FIFO_COUNTL.

### 8.42 REGISTER 116 – FIFO READ WRITE

**Register Name:** FIFO\_R\_W

**Register Type:** READ/WRITE

**Register Address:** 116 (Decimal); 74 (Hex)

BIT	NAME	FUNCTION
[7:0]	FIFO_DATA[7:0]	Read/Write command provides Read or Write operation for the FIFO.

**Description:**

This register is used to read and write data from the FIFO buffer.

Data is written to the FIFO in order of register number (from lowest to highest). If all the FIFO enable flags (see below) are enabled, the contents of registers 59 through 72 will be written in order at the Sample Rate.

The contents of the sensor data registers (Registers 59 to 72) are written into the FIFO buffer when their corresponding FIFO enable flags are set to 1 in FIFO\_EN (Register 35).

If the FIFO buffer has overflowed, the status bit *FIFO\_OVERFLOW\_INT* is automatically set to 1. This bit is located in INT\_STATUS (Register 58). When the FIFO buffer has overflowed, the oldest data will be lost and new data will be written to the FIFO unless register 26 CONFIG, bit[6] FIFO\_MODE = 1.

If the FIFO buffer is empty, reading register FIFO\_DATA will return a unique value of 0xFF until new data is available. Normal data is precluded from ever indicating 0xFF, so 0xFF gives a trustworthy indication of FIFO empty.



### 8.43 REGISTER 117 – WHO AM I

**Register Name:** WHO\_AM\_I

**Register Type:** READ only

**Register Address:** 117 (Decimal); 75 (Hex)

BIT	NAME	FUNCTION
[7:0]	WHOAMI	Register to indicate to user which device is being accessed.

This register is used to verify the identity of the device. The contents of *WHOAMI* is an 8-bit device ID. The default value of the register is 0x19. This is different from the I<sup>2</sup>C address of the device as seen on the slave I<sup>2</sup>C controller by the applications processor. The I<sup>2</sup>C address of the MPU-6886 is 0x68 or 0x69 depending upon the value driven on ADO pin.

### 8.44 REGISTERS 119, 120, 122, 123, 125, 126 ACCELEROMETER OFFSET REGISTERS

**Register Name:** XA\_OFFSET\_H

**Register Type:** READ/WRITE

**Register Address:** 119 (Decimal); 77 (Hex)

BIT	NAME	FUNCTION
[7:0]	XA_OFFS[14:7]	Upper bits of the X accelerometer offset cancellation. ±16g Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps.

**Register Name:** XA\_OFFSET\_L

**Register Type:** READ/WRITE

**Register Address:** 120 (Decimal); 78 (Hex)

BIT	NAME	FUNCTION
[7:1]	XA_OFFS[6:0]	Lower bits of the X accelerometer offset cancellation. ±16g Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps.
[0]	-	Reserved.

**Register Name:** YA\_OFFSET\_H

**Register Type:** READ/WRITE

**Register Address:** 122 (Decimal); 7A (Hex)

BIT	NAME	FUNCTION
[7:0]	YA_OFFS[14:7]	Upper bits of the Y accelerometer offset cancellation. ±16g Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps

**Register Name:** YA\_OFFSET\_L

**Register Type:** READ/WRITE

**Register Address:** 123 (Decimal); 7B (Hex)

BIT	NAME	FUNCTION
[7:1]	YA_OFFS[6:0]	Lower bits of the Y accelerometer offset cancellation. ±16g Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps
[0]	-	Reserved.

**Register Name: ZA\_OFFSET\_H**

**Register Type: READ/WRITE**

**Register Address: 125 (Decimal); 7D (Hex)**

BIT	NAME	FUNCTION
[7:0]	ZA_OFFS[14:7]	Upper bits of the Z accelerometer offset cancellation. $\pm 16g$ Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps

**Register Name: ZA\_OFFSET\_L**

**Register Type: READ/WRITE**

**Register Address: 126 (Decimal); 7E (Hex)**

BIT	NAME	FUNCTION
[7:1]	ZA_OFFS[6:0]	Lower bits of the Z accelerometer offset cancellation. $\pm 16g$ Offset cancellation in all Full Scale modes, 15 bit 0.98-mg steps
[0]	-	Reserved.

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## 9 USE NOTES

### 9.1 ACCELEROMETER-ONLY LOW-NOISE MODE

The first output sample in Accelerometer-Only Low-Noise Mode after wake up from sleep always has 1 ms delay, independent of ODR.

### 9.2 ACCELEROMETER LOW-POWER MODE

Changing the value of SMPLRT\_DIV register in Accelerometer Low-Power mode will take effect after up to one sample at the old ODR.

### 9.3 SENSOR MODE CHANGE

When switching from low-power modes to low-noise modes, unsettled output samples may be observed at the gyroscope or accelerometer outputs due to filter switching and settling. The number of unsettled output samples depends on the filter and ODR settings. The number of unsettled output samples is minimized by selecting the widest low-noise-mode filter bandwidth consistent with the chosen ODR.

### 9.4 TEMP SENSOR DURING GYROSCOPE STANDBY MODE

During transition from Gyro Low power mode (GYRO\_CYCLE=1), to Gyro Standby mode, in addition to the Gyro axis (axes) being turned off, the Temp Sensor will also be turned off if the Accel is disabled. In order to keep the temp sensor on during Gyroscope standby mode when Accel is disabled, the following procedure should be followed:

- Set GYRO\_CYCLE = 0 at least one ODR cycle prior to entering Standby mode
- At least one of the Gyro axis is ON prior to entering Standby mode
- Set GYRO\_STANDBY = 1

### 9.5 GYROSCOPE MODE CHANGE

Gyroscope will take one ODR clock period to switch from Low-Noise to Low-Power mode after GYRO\_CYCLE bit is set.

If GYRO\_CYCLE is set to 1 prior to turning on the gyroscope, the first sample will be from low-noise mode, which may not be a settled value. Ignoring the first reading is recommended in this case.

### 9.6 POWER MANAGEMENT 1 REGISTER SETTING

It is required to set CLKSEL[2:0] to 001 (auto-select) for full performance.

### 9.7 UNLISTED REGISTER LOCATIONS

Do not read unlisted register locations in Sleep mode as this may cause the device to hang up, requiring power cycle to restore operation.

### 9.8 CLOCK TRANSITION WHEN GYROSCOPE IS TURNED OFF

When the gyroscope is on, the on-chip master clock source will be the gyroscope clock (assuming CLKSEL[2:0] = 001 for auto-select mode); otherwise, the master clock source will be the internal oscillator as long as the part is not in Sleep mode. During a power mode transition, whenever the gyroscope is disabled and the part enters a mode other than Sleep, the on-chip master clock source will transition from the gyroscope clock to the internal oscillator. It will take about 20  $\mu$ s for this transition to complete.

## 9.9 SLEEP MODE

The part will only enter Sleep mode when the SLEEP bit in PWR\_MGMT\_2 is set to '1'. If SLEEP bit is '0' and bit STBY\_[X,Y,Z]A and STBY\_[X,Y,Z]G are all set to '1', accelerometer and gyroscope will be turned off, but the on-chip master clock will still be running and consuming power.

## 9.10 NO SPECIAL OPERATION NEEDED FOR FIFO READ IN LOW POWER MODE

The use of FIFO is enabled in all modes including low power mode.

## 9.11 GYROSCOPE STANDBY PROCEDURE

The follow precaution and procedure must be followed while using the Gyroscope Standby mode:

### Precaution to follow while entering Standby Mode:

- The user will ensure that at least one gyro axis is ON when setting gyro\_standby = 1.

Procedure to transition from Gyro Standby to Gyro off:

- The user should set gyro\_standby = 0 first
- Next, turn off gyro x/y/z.

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## 10 ASSEMBLY

This section provides general guidelines for assembling InvenSense Micro Electro-Mechanical Systems (MEMS) gyros packaged in LGA package.

### 10.1 ORIENTATION OF AXES

The diagram below shows the orientation of the axes of sensitivity and the polarity of rotation. Note the pin 1 identifier (•) in the figure.

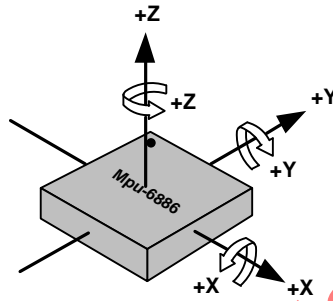


Figure 12. Orientation of Axes of Sensitivity and Polarity of Rotation

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**10.2 PACKAGE DIMENSIONS**

24 Lead LGA (3x3x0.75) mm NiAu pad finish

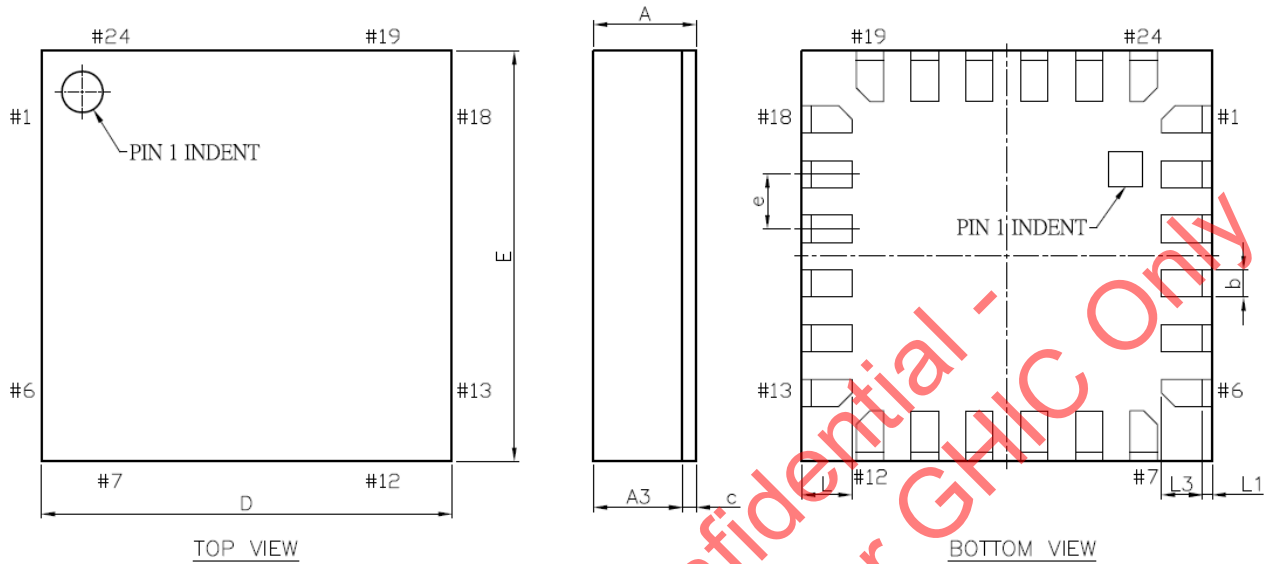


Figure 13. Package Diagram

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A3	---	0.65 REF.	---
b	0.15	0.20	0.25
c	---	0.10 REF.	---
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	---	0.40	---
L	0.32	0.37	0.42
L1	0.02	0.07	0.12
L3	0.25	0.30	0.35
y	0.00	---	0.08

Table 20. Package Dimensions

## 11 PART NUMBER PACKAGE MARKING

The part number package marking for MPU-6886 devices is summarized below:

PART NUMBER	PART NUMBER PACKAGE MARKING
MPU-6886	I66

Table 21. Part Number Package Marking

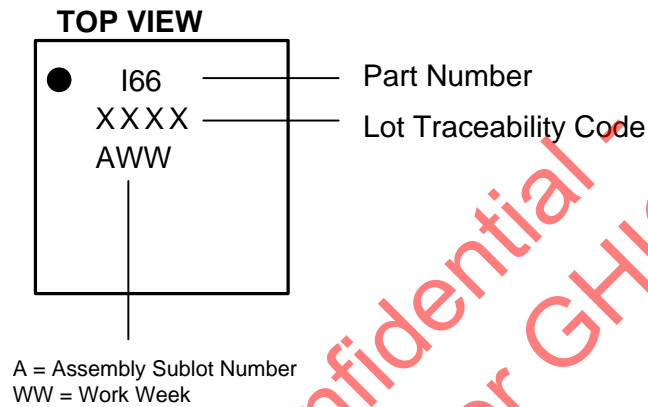


Figure 14. Part Number Package Marking

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## 12 REFERENCE

Please refer to “InvenSense MEMS Handling Application Note (AN-IVS-0002A-00)” for the following information:

- Manufacturing Recommendations
  - Assembly Guidelines and Recommendations
  - PCB Design Guidelines and Recommendations
  - MEMS Handling Instructions
  - ESD Considerations
  - Reflow Specification
  - Storage Specifications
  - Package Marking Specification
  - Tape & Reel Specification
  - Reel & Pizza Box Label
  - Packaging
  - Representative Shipping Carton Label
- Compliance
  - Environmental Compliance
  - DRC Compliance
  - Compliance Declaration Disclaimer

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## 13 DOCUMENT INFORMATION

### 13.1 REVISION HISTORY

Revision Date	Revision	Description
12/20/2016	1.0	Initial Release
03/29/2017	1.1	Updated Sections 1, 2, 4, 8, 10

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